

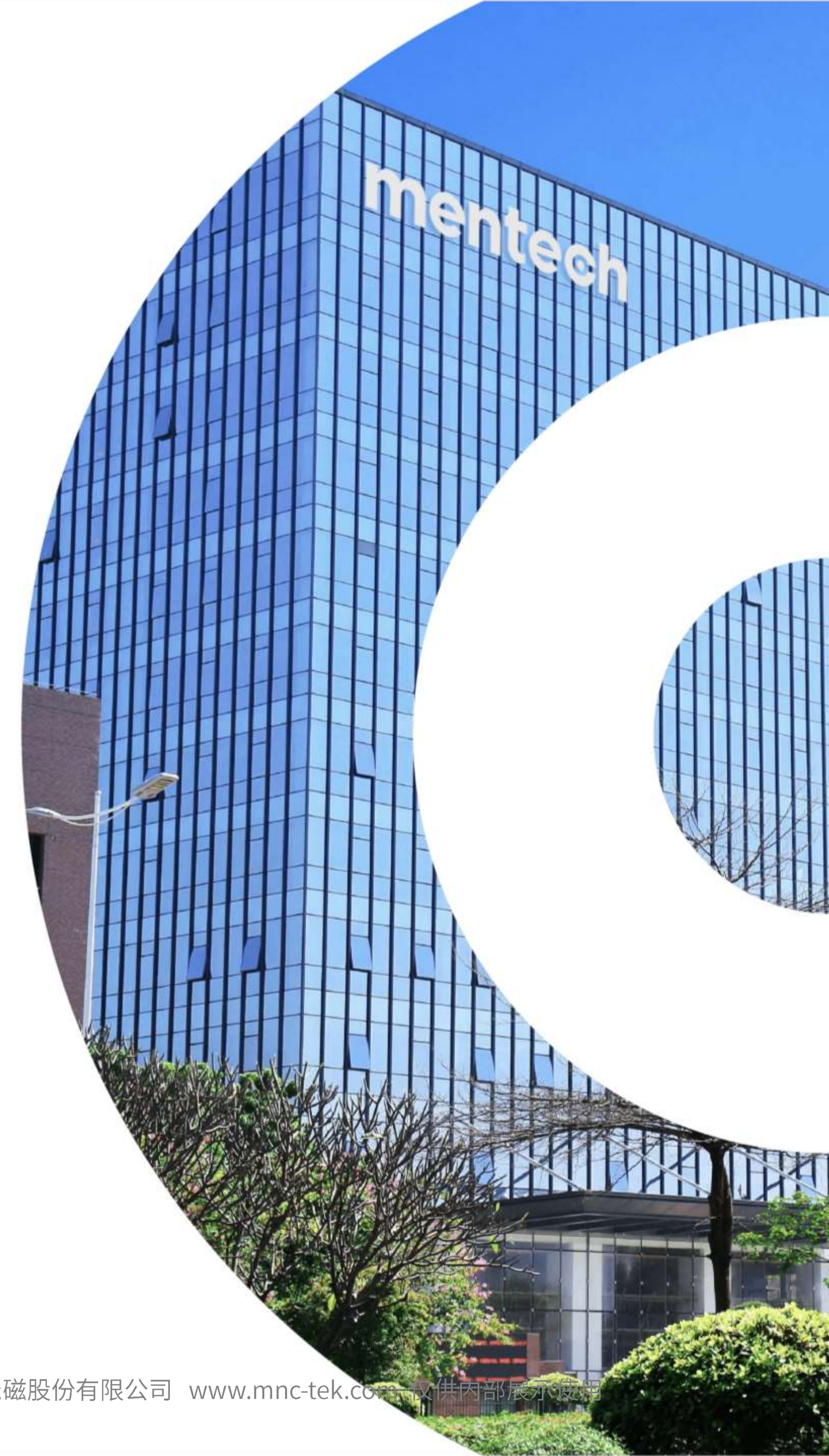


Optical Business Unit

23th Sep 2022 Date
2022 V3 Version

Dongguan Mentech Optical & Magnetic Co., Ltd.

- 01 | Overview
- 02 | R&D Ability
- 03 | Manufacturing
- 04 | Quality Assurance
- 05 | Key products





Overview

An aerial photograph of a city with several high-rise buildings, some with green roofs. A large blue diagonal shape is overlaid on the top right. A white banner with a blue circular element on the left contains the text '01 Overview'.

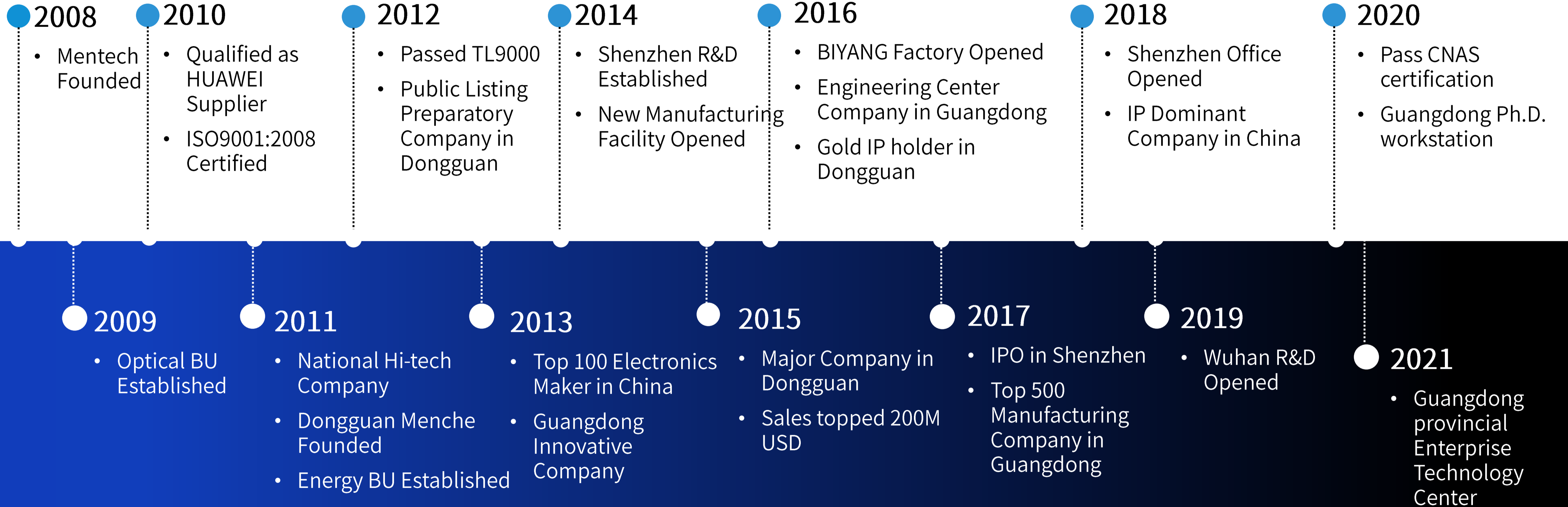
01 Overview

Optical BU Strategic Positioning

Dedicated to optics/optical modules with a focus on provision of OEM/ODM services to industry users



Optical BU-Milestones



Optical BU – R&D/Manufacturing Facilities



Shenzhen R & D Center



Wuhan R & D Center



Dongguan R & D Center

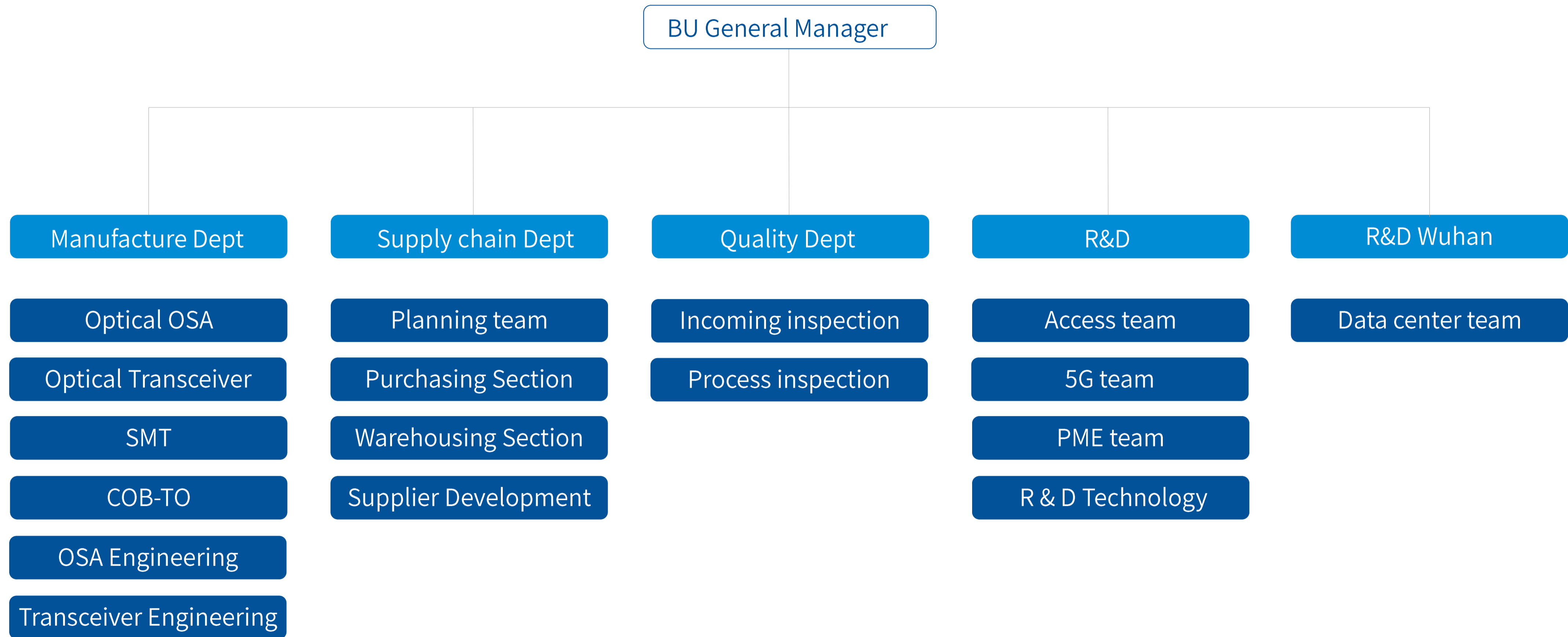


Dongguan | Production base



Biyang | Production base

Optical BU – O-chart





R & D Ability





R & D Ability





5G&
Access

Chen Cong

General Manager

Postdoctoral, senior engineer

8 SCI papers

20 authorized patents

More than 10 Conference Papers

Participated in drafting more than 10 industry standards



Data Com-
munication

Qian Yinbo

General Manager

Postdoctoral, senior engineer

More than 10 SCI papers

26 authorized patents

Won the best paper award in the world

Won the first prize of science and technology of China communication society



OSA
products

Wang Huitao

Chief engineer

Doctor

More than 10 SCI papers

6 authorized patents

Participated in drafting 2 industry standards

Manufacturing-R&D Support



WH

- 30 engineers
- Focus on Data Center
- 400G SR8
- 100G SR4/AOC
- 40G SR4/AOC
- 25G SR/AOC
- 10G SR/AOC
- 100G CWDM4/LR4
- 40G LR4/PSM4



5G

- 16 engineers
- Focus on 5G wireless
- 25G MWDM
- 25G LWDM
- 25G CWDM
- 25G LR/LR lite
- 25G BIDI
- SFP+
- XFP
- SFP



DG

- 14 engineers
- Focus on PON
- 10G ONU BOSA
- ONU BOSA
- 10G ONU Module
- ONU Module
- XG(S)&GPON COMBO OLT
- XG(S)-PON OLT
- 10G EPON OLT
- GPON OLT
- EPON OLT



Platform

- 9 engineers
- Focus on platform
- PME
- TE
- CE
- Etc.



LD CHIP Team

- 6 engineers
- Wafer FA/ characterization
- Wafer Fabrication
- Vacuum Process
- Wafer bonding/Lapping
- Optical testing metrology
- Semi-conduct Equipment




TO/COB Team

- 6 engineers
- COB process
- DB/WB
- TO Process



OSA Team

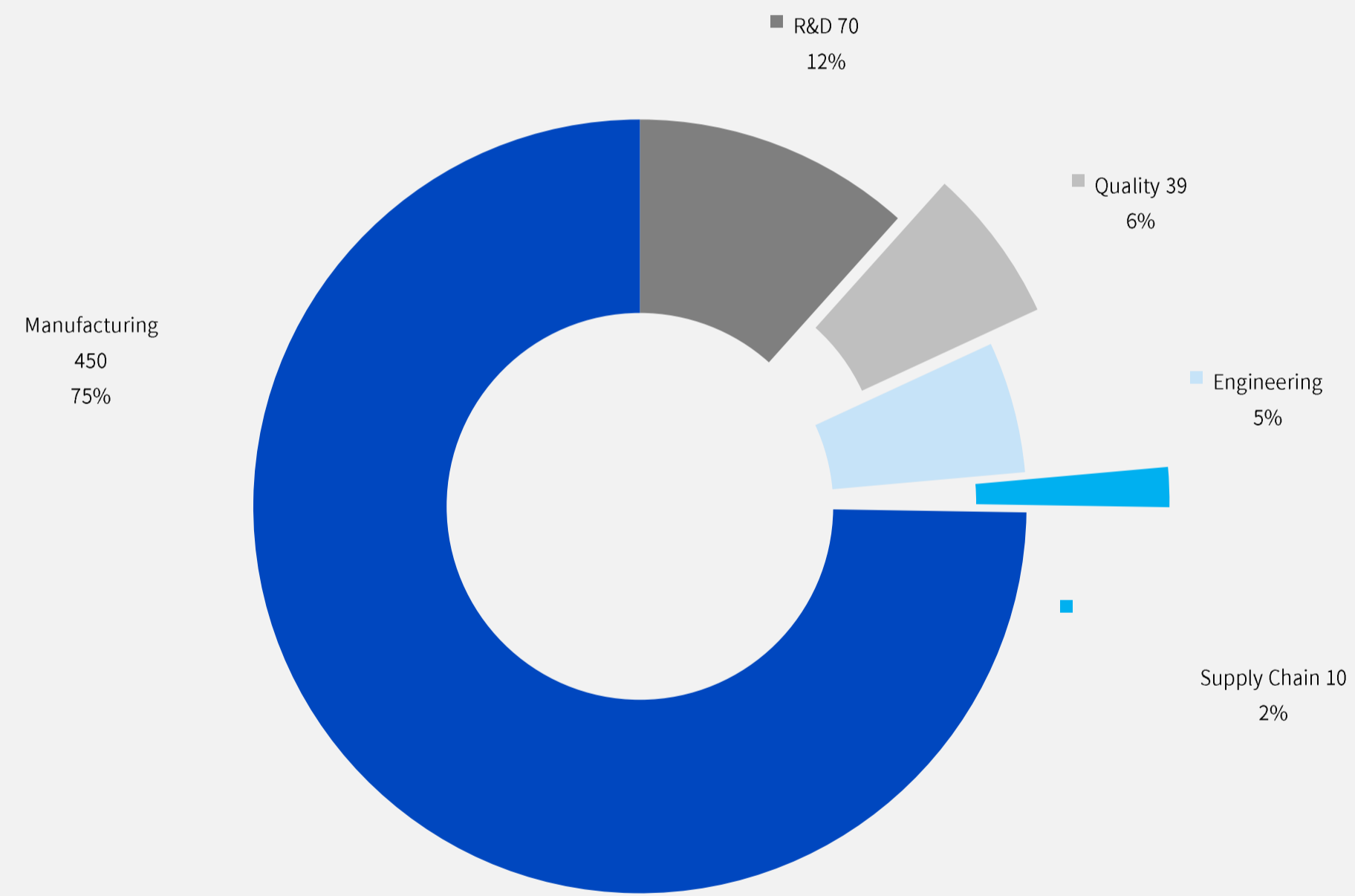
- 9 engineers
- Filter Bonding
- Active Alignment
- Laser Welding
- Burn-in



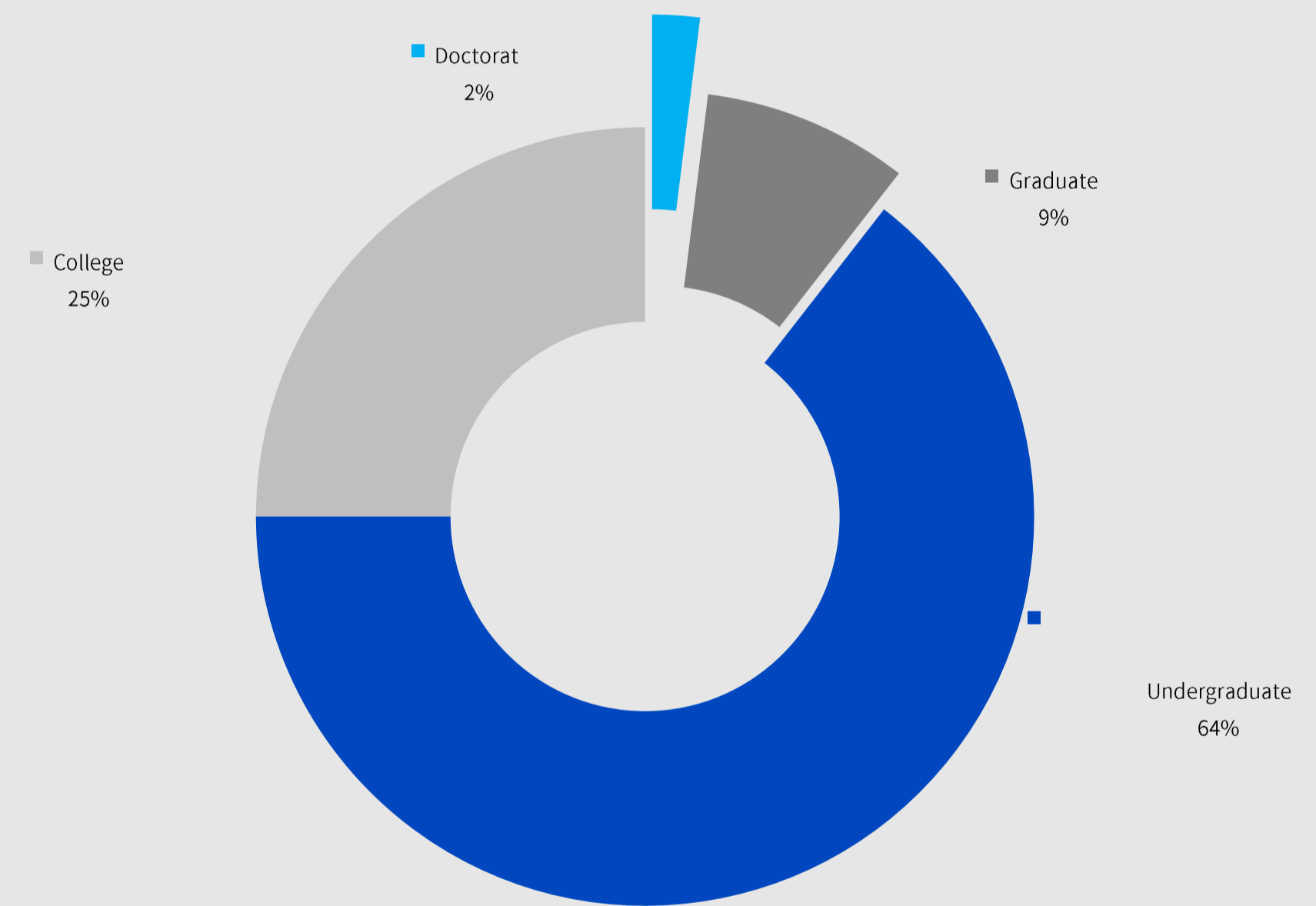
Module Team

- 12 engineers
- Hot-Bar soldering
- Calibration
- Burn-in
- Temperature Testing

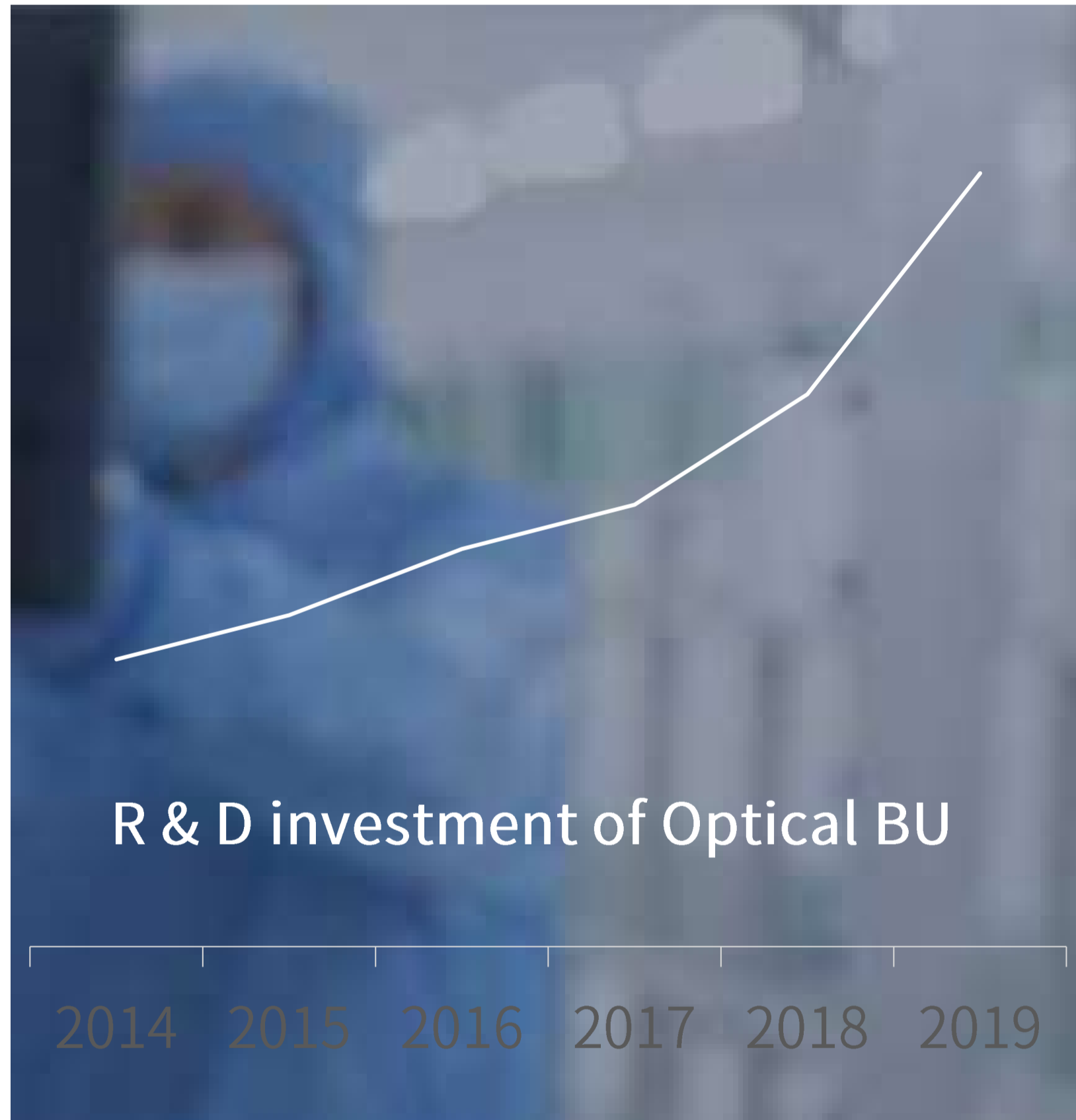
Optical BU – Personnel Composition



Personnel Composition



Personnel Education Background



Mentech attaches great importance to improving scientific and technological strength and product quality , R & D investment is maintained at 5% - 7% of business income. Continuously research and develop new technology, new products, to provide customers with more optimized solutions.





Manufacturing



03

Manufacturing

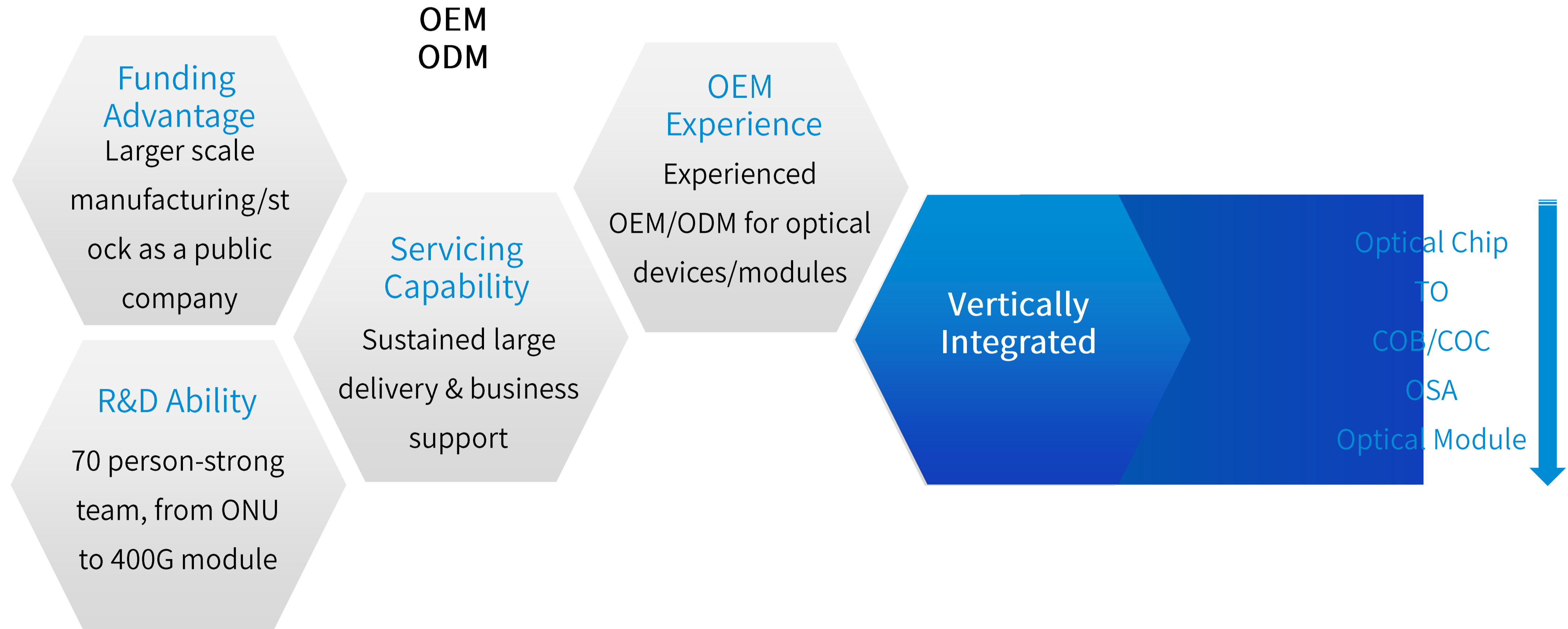


80%

Transformation and upgrade to smart factory

Intelligent production mode is one of the key points in Mentech's development. Our Optical, Electronics, and Power BUs have achieved large-scale automated production and customized automation. We continue to cooperate with automation manufacturers to develop equipment to meet the needs of more customers.

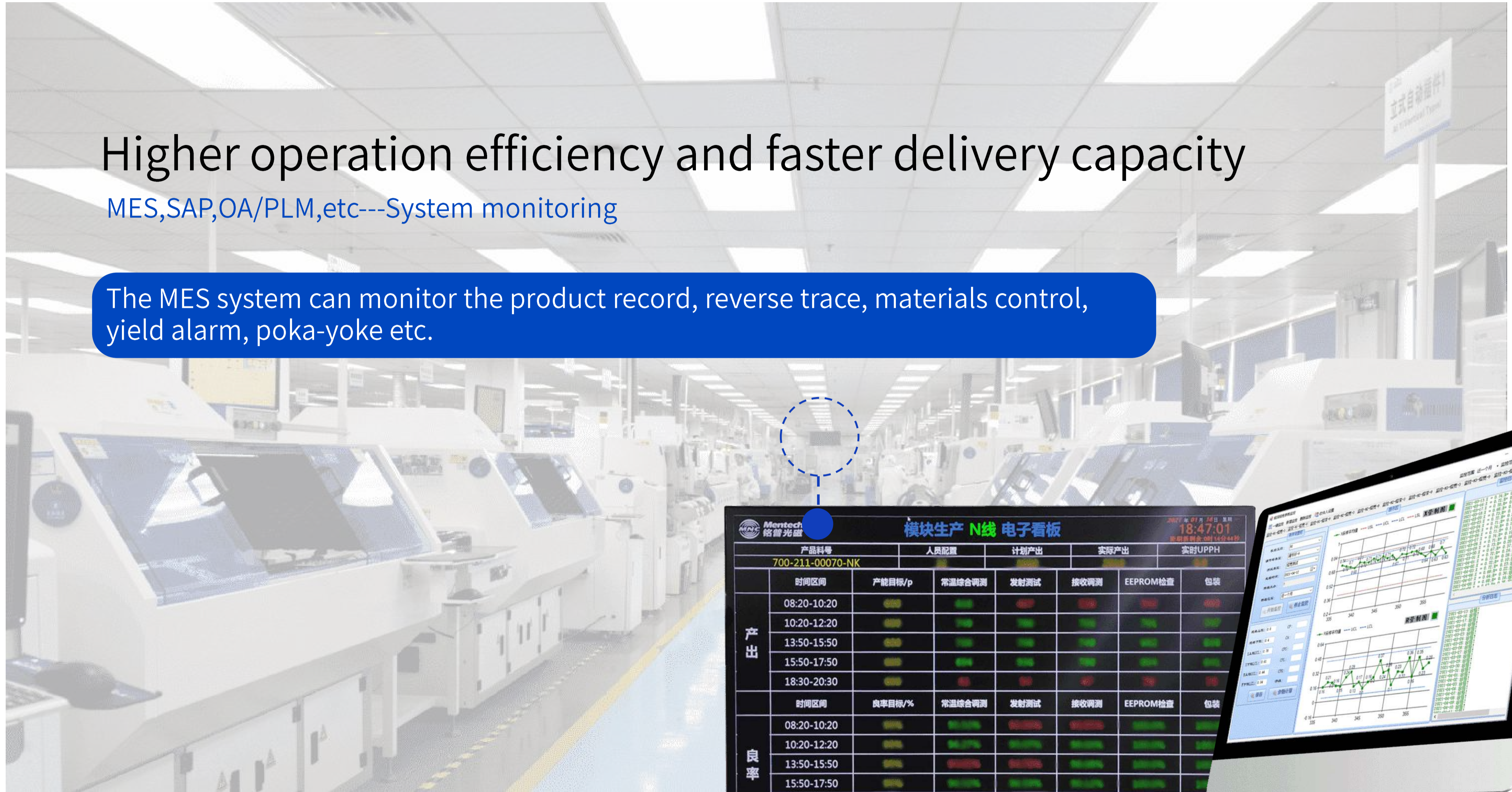
Manufacturing-OEM/ODM Services



Higher operation efficiency and faster delivery capacity

MES,SAP,OA/PLM,etc---System monitoring

The MES system can monitor the product record, reverse trace, materials control, yield alarm, poka-yoke etc.



Mentech 铭普光磁

模块生产 N线 电子看板

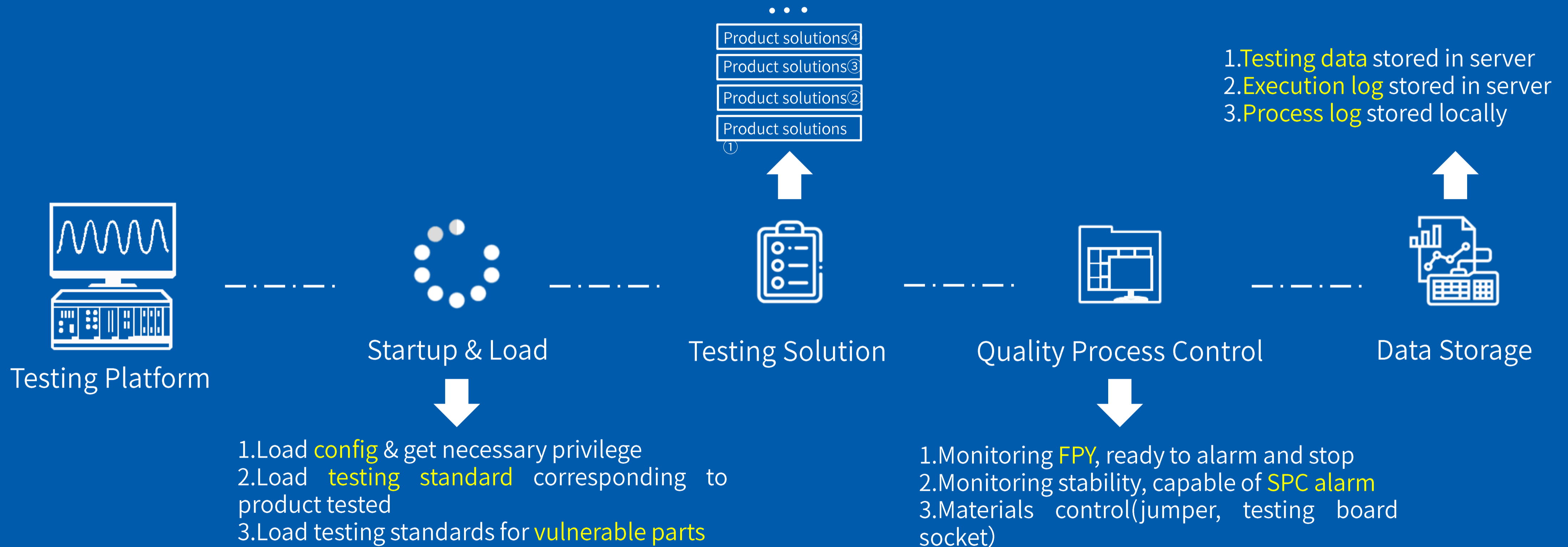
18:47:01

产品料号		人员配置	计划产出	实际产出	实时UPPH		
700-211-00070-NK							
产出	时间区间	产能目标/p	常温综合调测	发射测试	接收调测	EEPROM检查	包装
	08:20-10:20						
	10:20-12:20						
	13:50-15:50						
	15:50-17:50						
18:30-20:30							
良率	时间区间	良率目标/%	常温综合调测	发射测试	接收调测	EEPROM检查	包装
	08:20-10:20						
	10:20-12:20						
	13:50-15:50						
	15:50-17:50						
18:30-20:30							



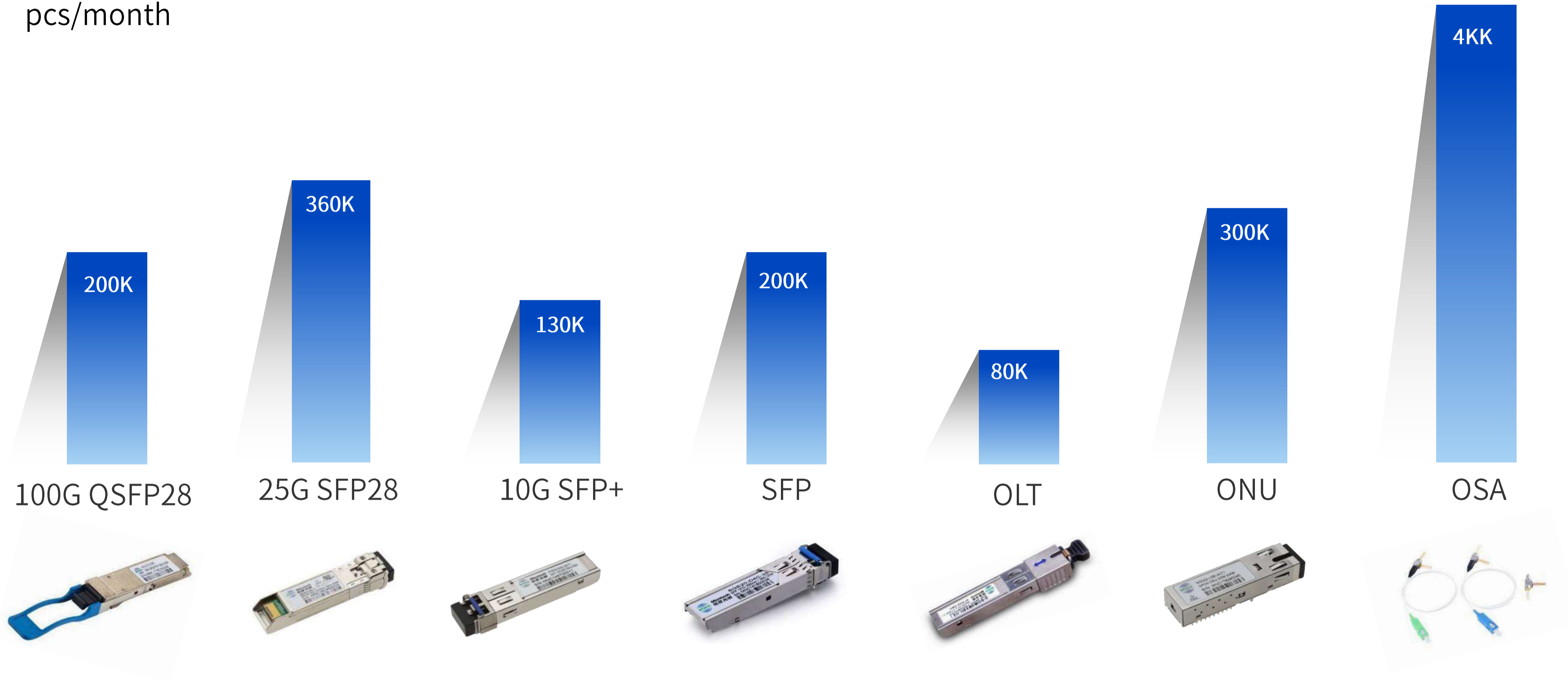
Manufacturing – Product Testing Platform

Modular testing platform, capable of rapid development to cater for needs of different customers/solutions

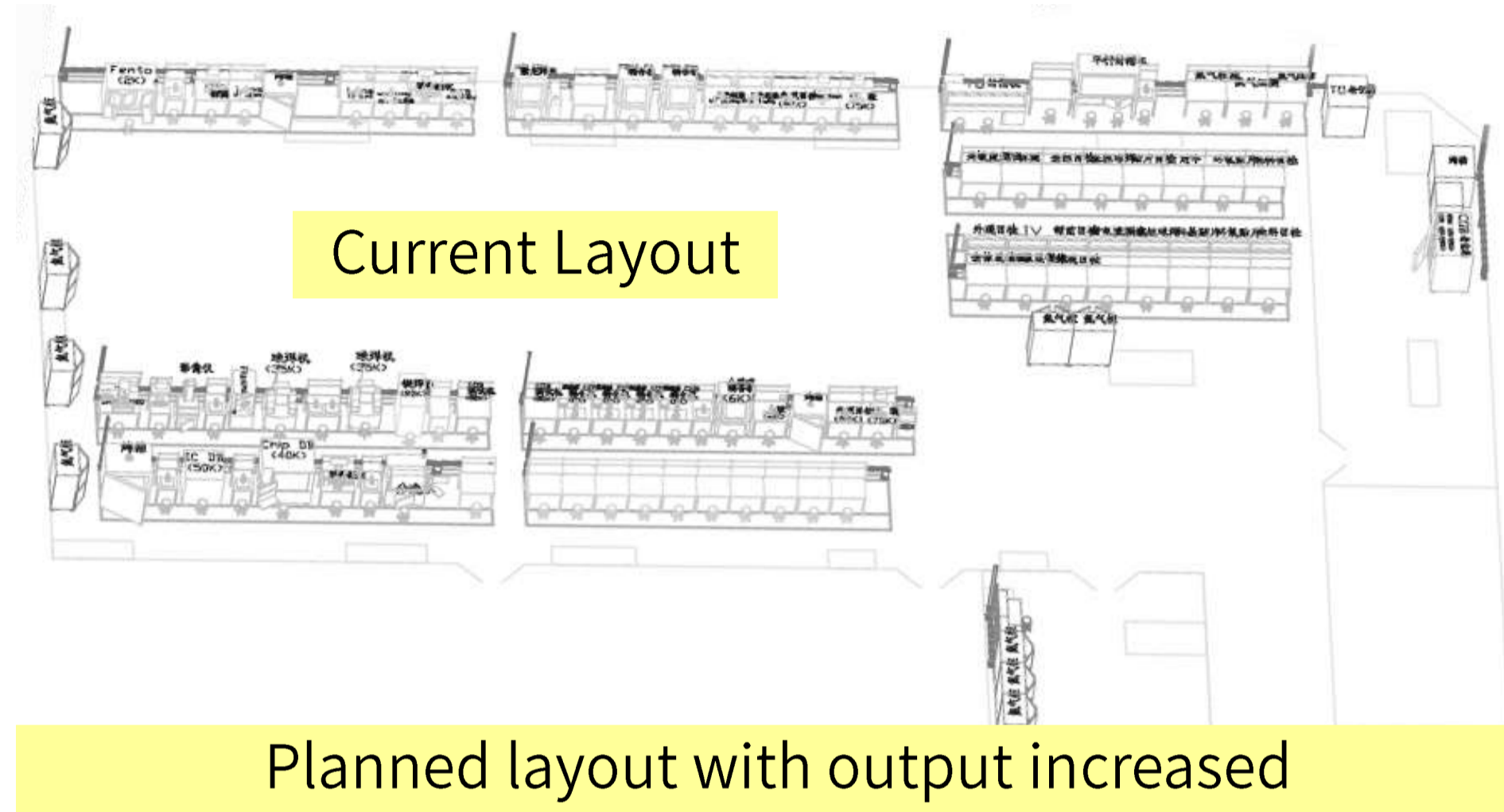


Manufacturing-Delivery Capability

pcs/month



Manufacturing-COB-TO Production Line Layout



Location

3F, Block #4, Dongguan

Area

700 square meters

COB Line Configuration

- Multi-mode COB automated line: 1
- Single-mode COB automated line: 1
- T046/T056 semi-automated line: 1 respectively
- T046/T056/T038 automated line: 3(planned)

Manufacturing-COB Production Line Equipment



Qty: 1
 Brand: Finelacer Femto
 Usage: COB surface mount, Soldering
 Precision: 0.5um
 Output: 10k/mth



Qty: 1
 Brand: PALOMAR
 Usage: COB surface mount, Optical chip die bond
 Precision: $\leq 5\mu\text{m}@3\text{sigma}$
 Output: 40k/mth



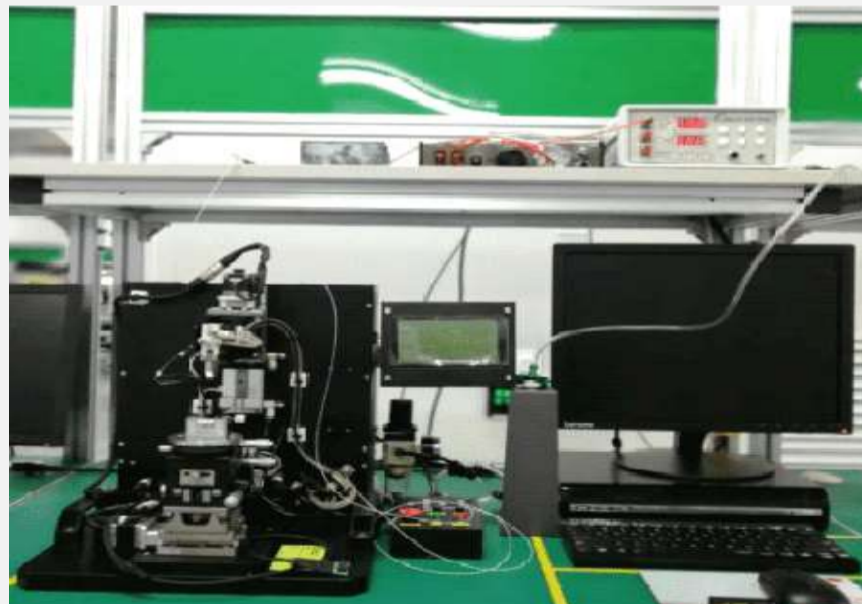
Qty: 1
 Brand: ENG
 Usage: COB surface mount LDD&TIA die bond
 Precision: $\leq 15\mu\text{m}@3\text{sigma}$
 Output: 60k/mth



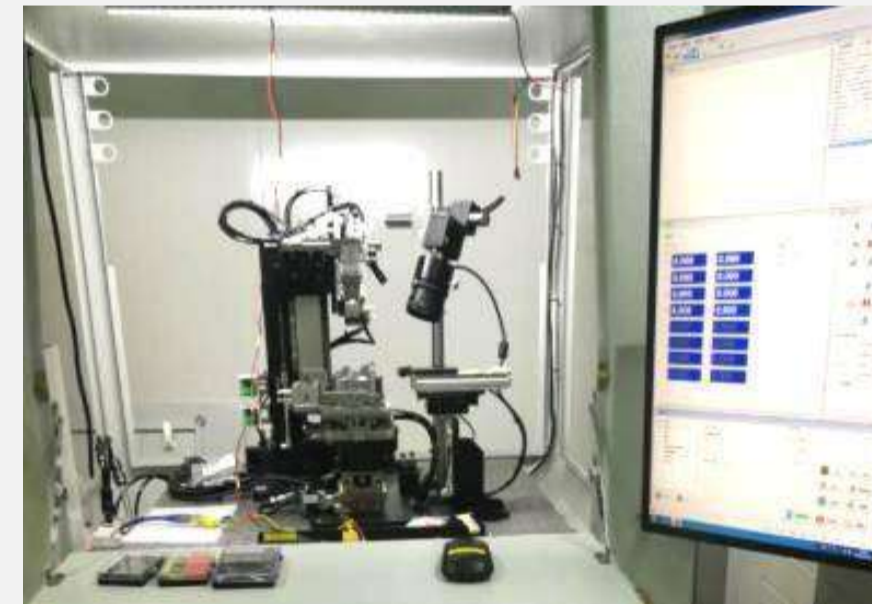
Qty: 2
 Brand: KS
 Usage: COB soldering
 Precision $\leq \pm 2.0\mu\text{m}$
 Output: 80k/mth



Qty: 1
 Brand: HESSE
 Usage: COB soldering
 Precision: $\leq \pm 3.0\mu\text{m}$
 Output: 40k/mth



Qty: 4
 Brand: home brand
 Usage: 25G automated coupling
 Precision: $\leq 0.1\mu\text{m}$
 Output: 40k/mth



Qty: 1
 Brand: home brand
 Usage: 100G automated coupling
 Precision: $\leq 0.1\mu\text{m}$
 Output 10k/mth



Qty: 1
 Brand: home brand
 Usage: Weathering VCSEL&DFB
 Output: Weathering 26K 25G COB & 10K 100G COB at once

Manufacturing-OSA Production Line Equipment



Qty: 1
Brand: Ultrasonic cleanser
Usage: Metal cleansing
Output: 1400k/mth



Qty: 2
Brand: Sinobonder
Usage: 0 degree glass surface mount
Output: 784k/mth



Qty: 2
Brand: Sinobonder
Usage: 45 degrees glass surface mount
Output: 784k/mth



Qty: 36
Brand: Sinobonder
Usage: TX coupling
Precision: $\leq \pm 2.0\mu m$
Output: 2400k/mth



Qty: 13
Brand: Sinobonder
Usage: RX coupling
Precision: $\leq \pm 5.0\mu m$
Output: 1092k/mth



Qty: 20
Brand: home brand
Usage: RX coupling
Precision: $\leq \pm 5.0\mu m$
Output: 1680k/mth



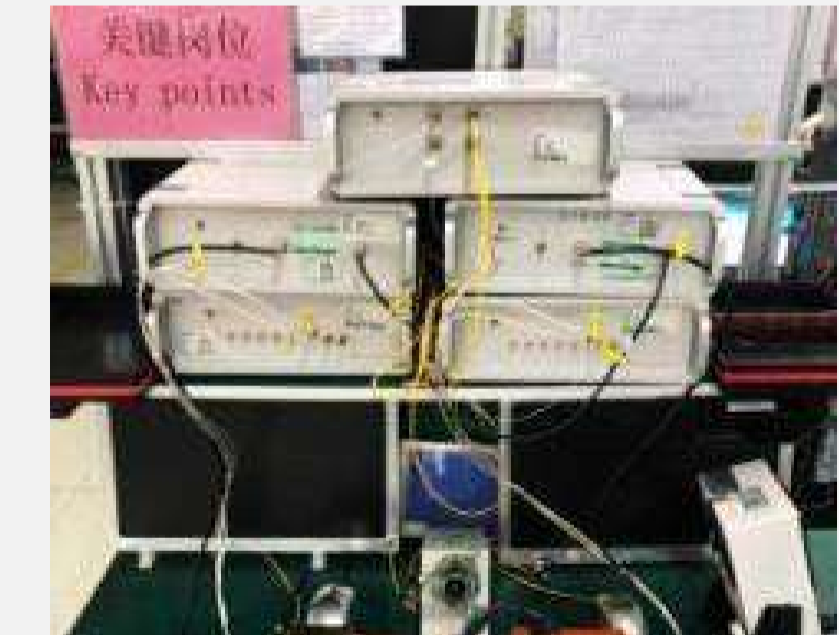
Qty: 8
Brand: sanwood
Usage: glue healing
Output: 2688k/mth



Qty: 17
Brand: sanwood
Usage: OSA Hi-low temp cycle
Output: 3800k/mth



Qty: 1
Brand: HAITUO
Usage: OSA-TE Hi-low temp testing
Output: 8.9k/mth



Qty: 24
Brand: home brand
Usage: BOSA testing
Output: 4700k/mth

Manufacturing-Module Production Line Equipment



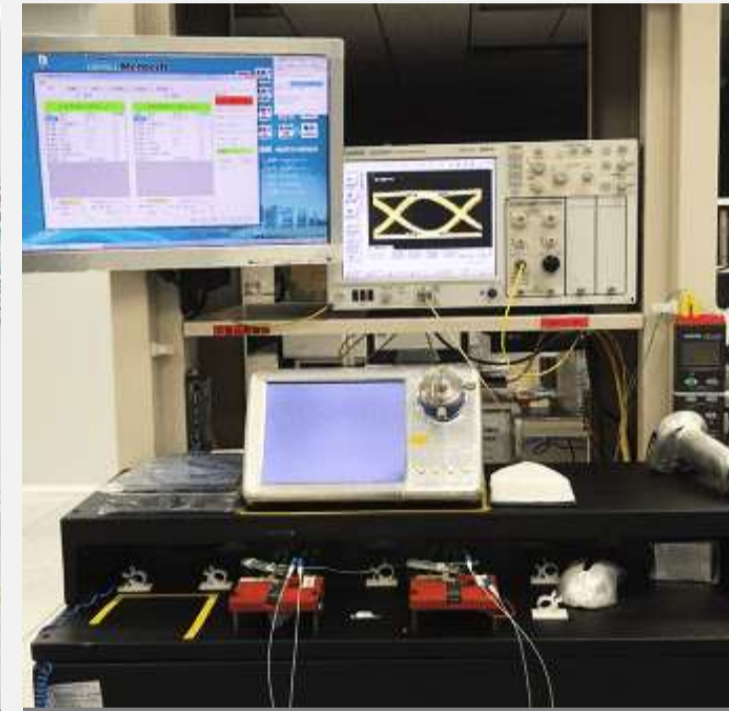
Name: high temp soldering
 Qty: 4
 Brand: techson
 Usage: Soft board soldering
 Precision: $\pm 0.1\text{mm}$
 Output: 20.8k/mth



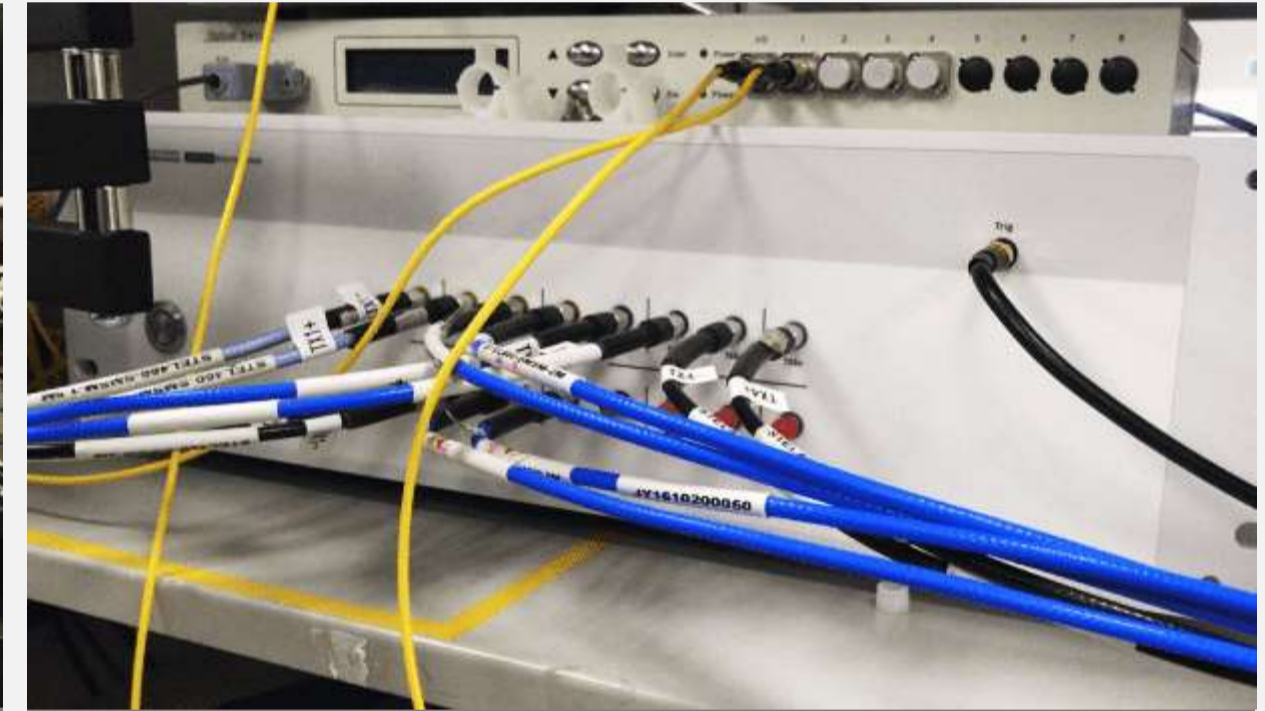
Name: X-RAY
 Brand: SCIENSCOPE
 Usage: High temp soldering inspection
 Output: 20.8k/mth



Qty: 6
 Brand: HAITUO
 Usage: Module temp adjust
 Precision: $\pm 1^\circ\text{C}$
 Output: 15.6k/mth



Name: Oscilloscope
 Qty: 33
 Brand: Agilent
 Usage: Eye diagram test
 Output: 624k/mth



Name: BER measurer
 Qty: 65
 Brand: stelight/home brand
 Usage: Bit error test
 Output: 624k/mth



Quality Assurance



04

Quality Assurance

Constantly updated quality management system.



▲ ISO9001-2015



▲ ISO14001-2015



▲ ISO45001-2018



▲ ISO/IEC 27001-2013



▲ ISO/IEC 17025-2017



▲ IATF 16949-2016



▲ TL9000-H R6.2/5.7



▲ ANSI/ESD S20.20-2014



▲ IECQ QC080000-2017



▲ GB/T 29490-2013



▲ GB/T 23001-2017

Our products meet the quality, safety, performance, EMC certification requirements of many countries.



TUV



CE



FCC



UL



IEC CB



TLC

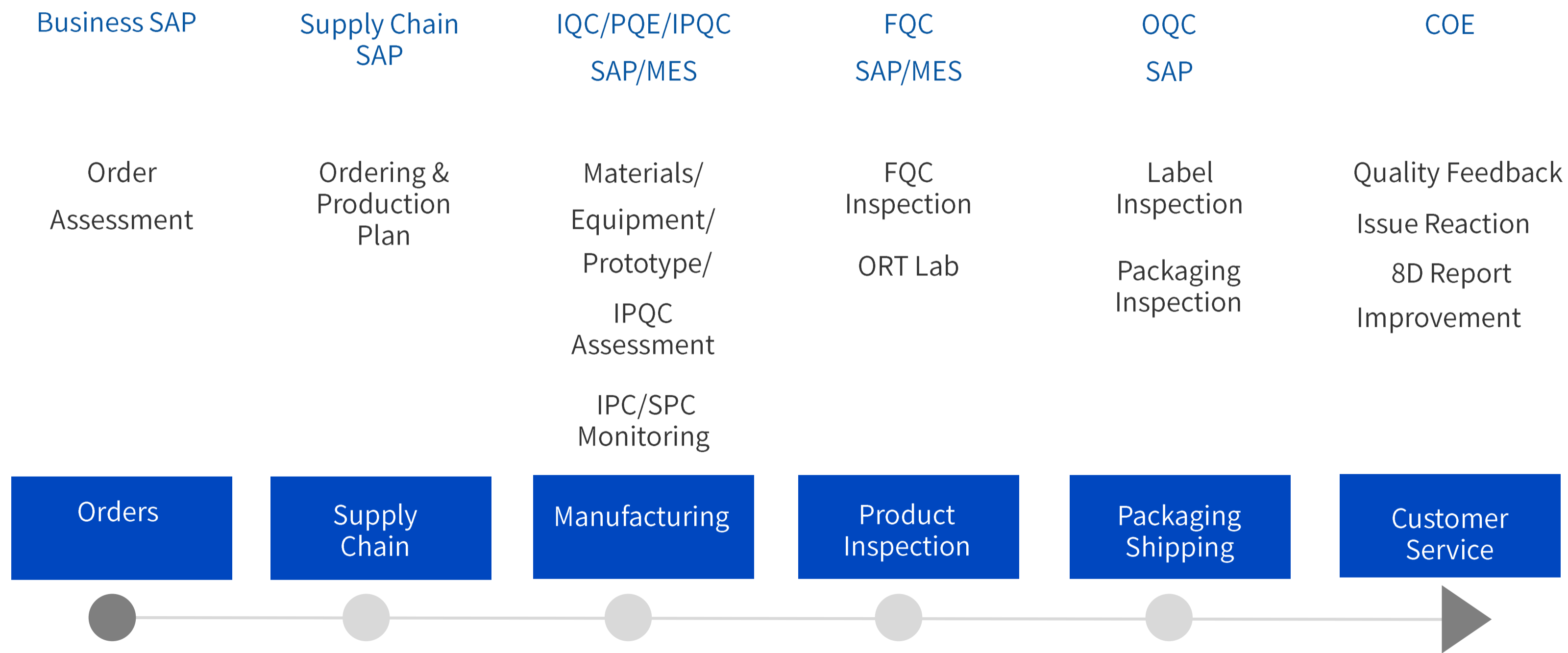


Wangrui



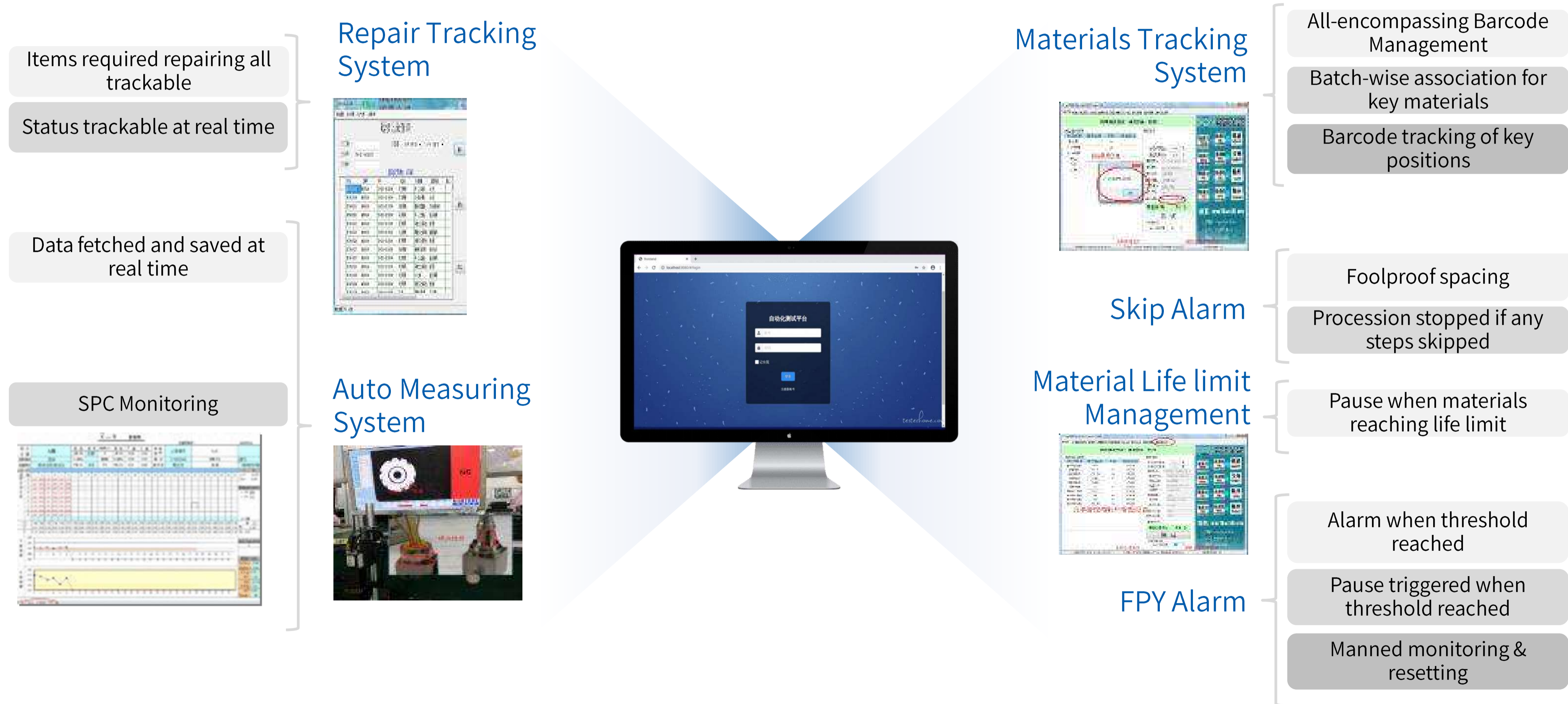
ROHS

QA- All-Encompassing



Customer Satisfaction

QA- Quality System



QA- Testing Capability

High and Low Temp Chamber

TEMP Range:
-40°C to +150 °C



Thermal Shock Chamber

TEMP Range:
:-40°C to +120 °C
Exchange Time:
5 mins
Duration:
30mins



Plating Thickness Tester

Non - destrutive
Plating thicknes
Compostion Analyer



Vibration Test

Simulating to Vibration during Transportation, Check the product Appearance/structu strength



2.5D Measurement Equipment

Accuracy:
1um



X-ray fluorescence analyzer

RoHS test



Metallic Microscope

Plating Thicknes
Soldering check



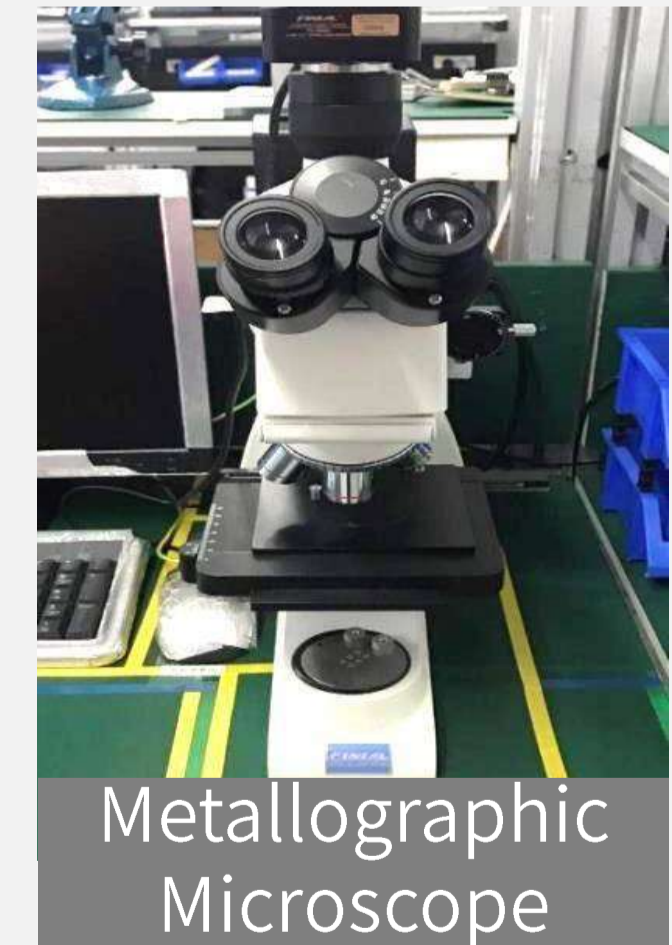
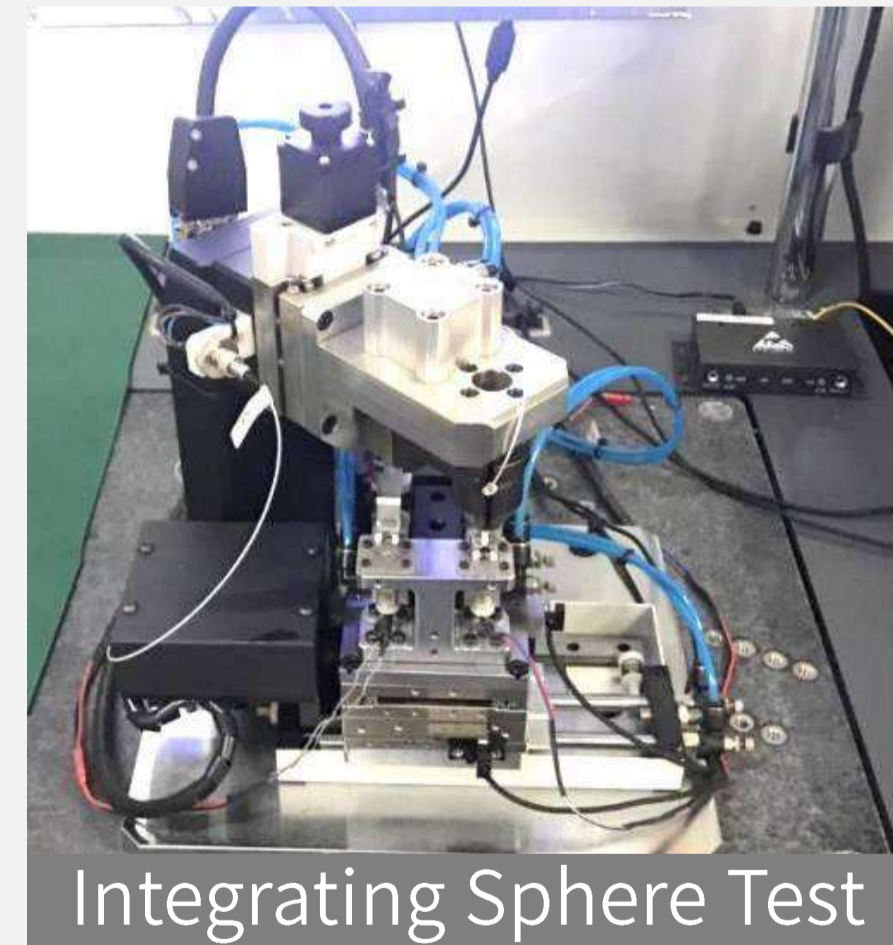
Salty Corrosion Tester

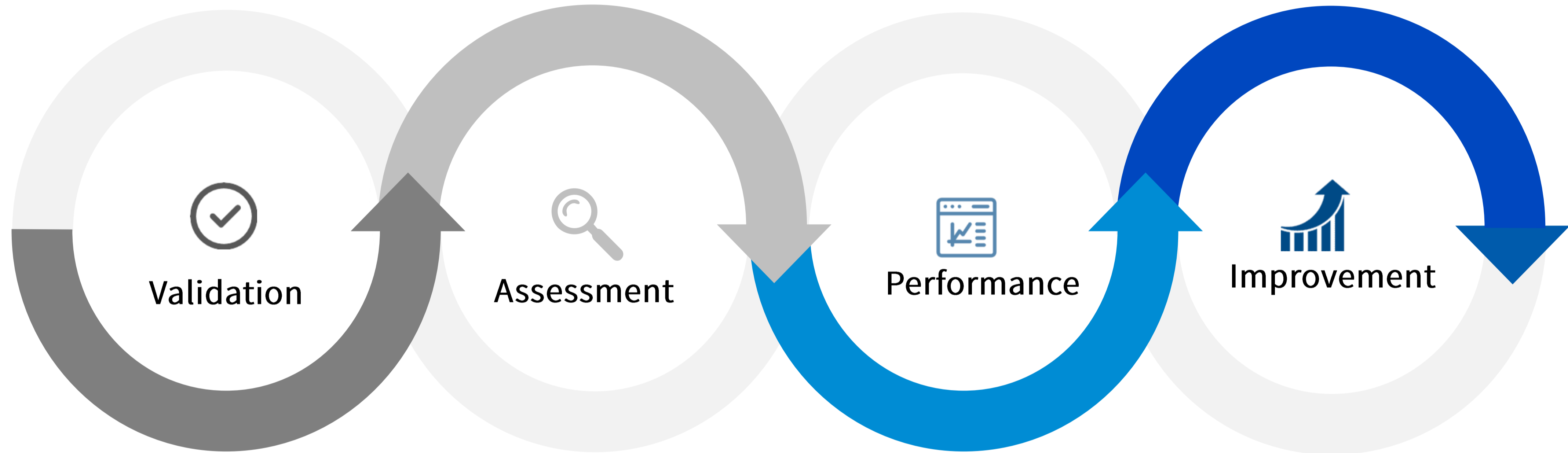
Simulating to out Door and check Product corrosion Resistance



A wide range of reliability tests can be conducted in our testing lab

QA- Intercept Testing Capability





Validation

Assessment

Performance

Improvement

Supplier Validation

Supplier Assessment

Supplier Performance

Supplier Improvement

Strict validation standard to ensure only high quality suppliers are introduced

Annual supplier assessment to prevent any lapse in quality

Pivot to suppliers with better performance in tests conducted regularly

Delegation for major incidents, Stay prepared for challenges

QA- Quality Principles



Pollution-free Safe
Production



Full Engagement for
Quality



Cut Waste
Eco-aware



Keep Promise
Keep Improving



Key products

05

key

products

100G QSFP28 series



FTTB

PON ONU/OLT

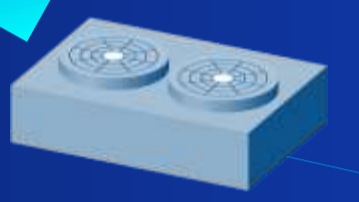


FTTH

((()))



SFP+/SFP28

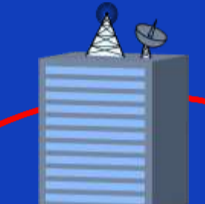


Data center



Edge

Wireless 4G/5G



WCB

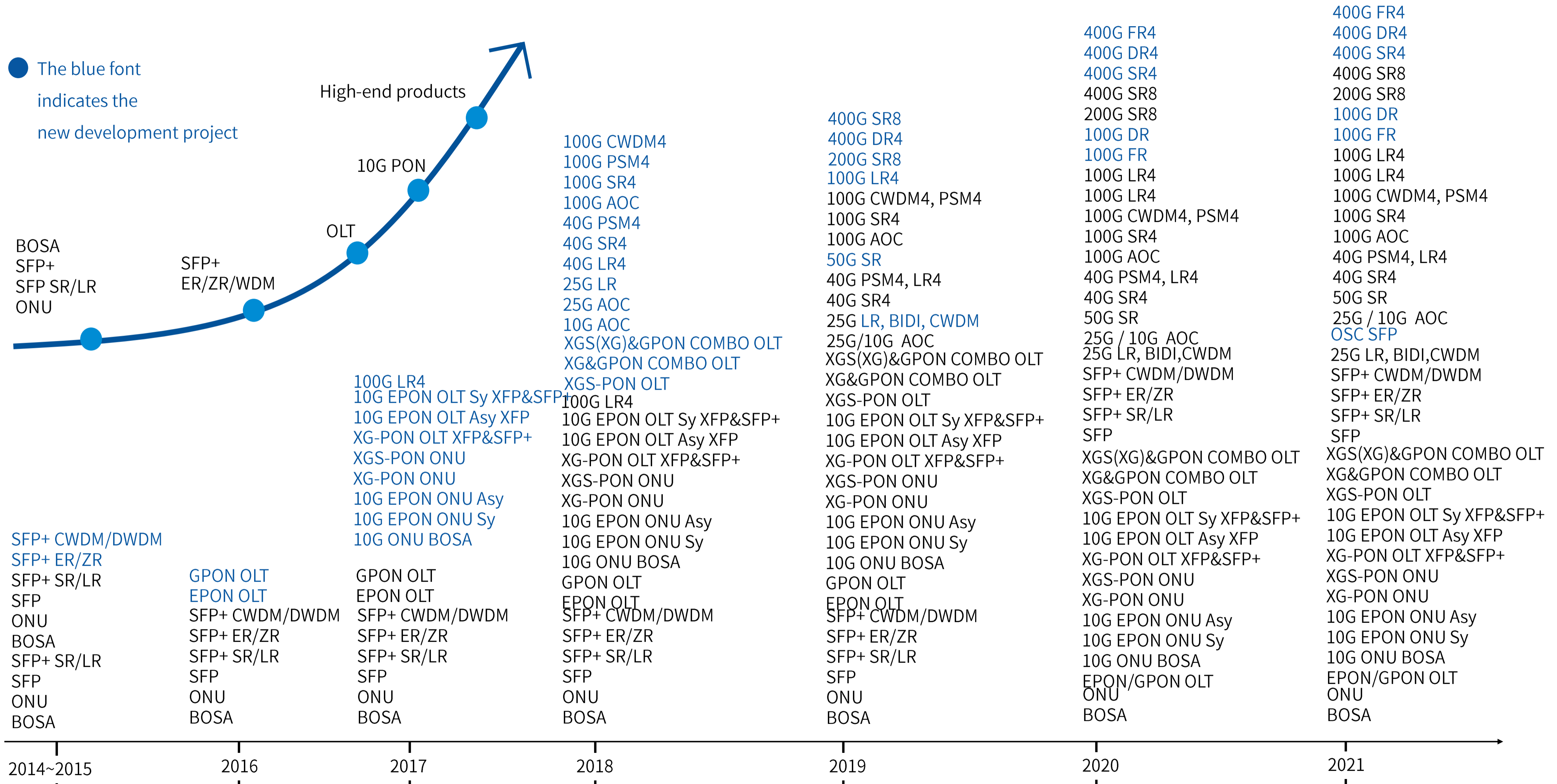


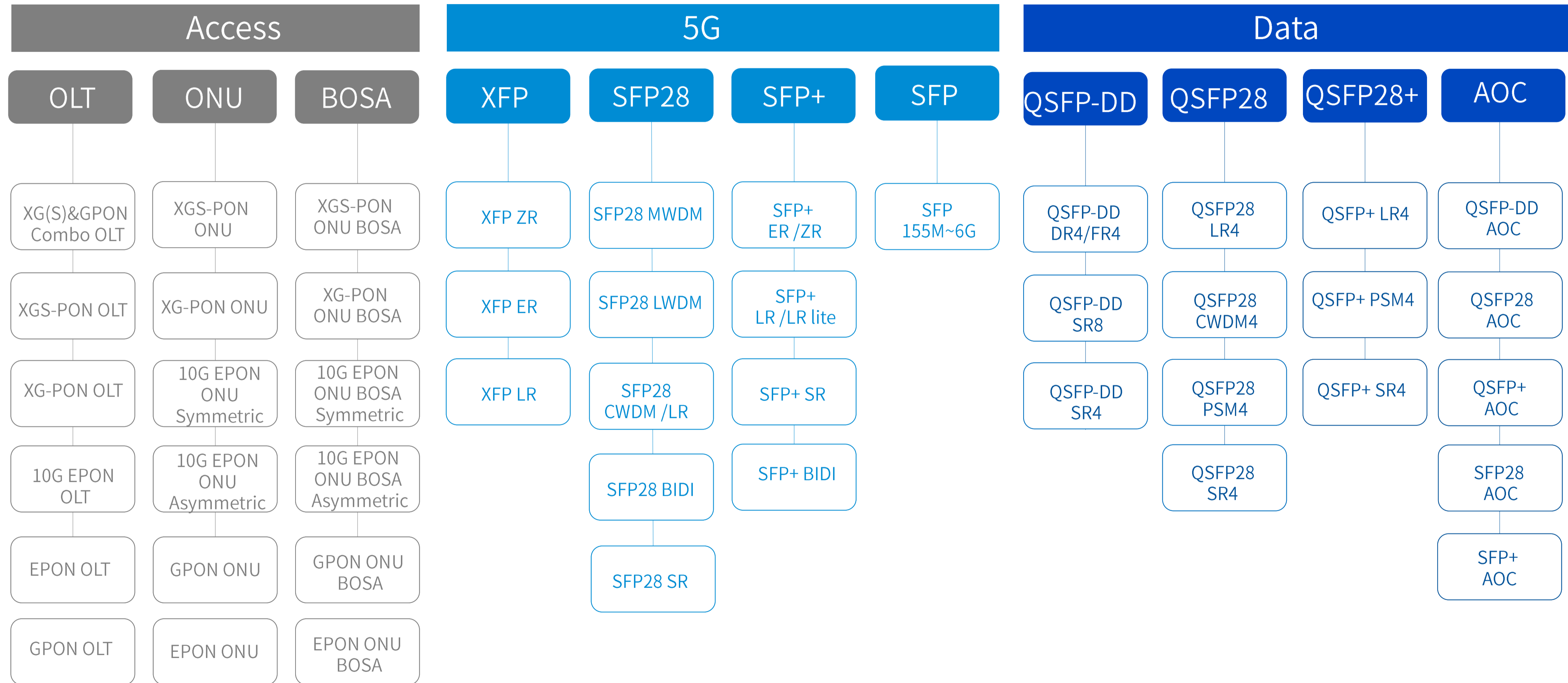
Trunk



SFP/SFP+/XFP/SFP28/QSFP28

Evolution of Mentech optical module





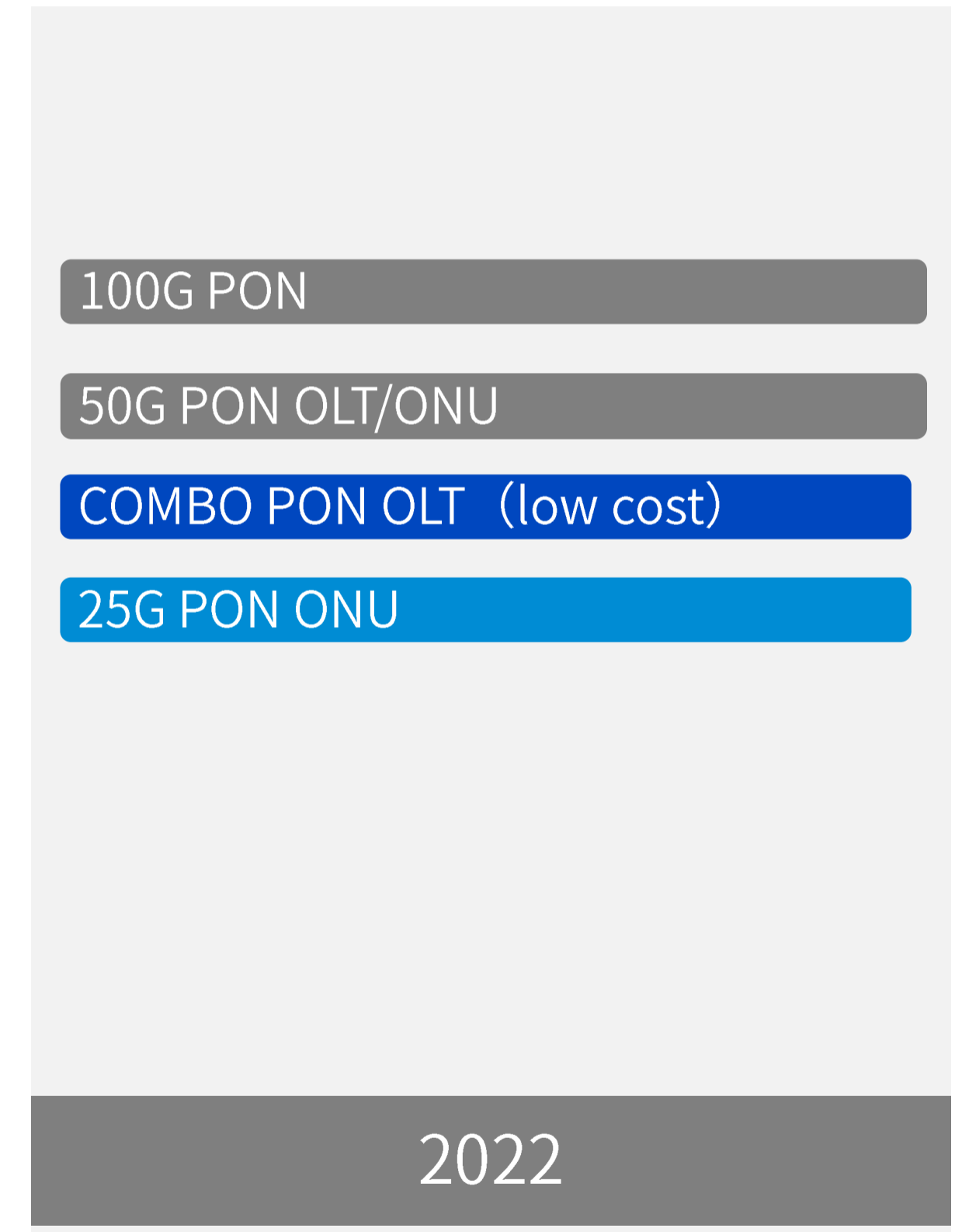
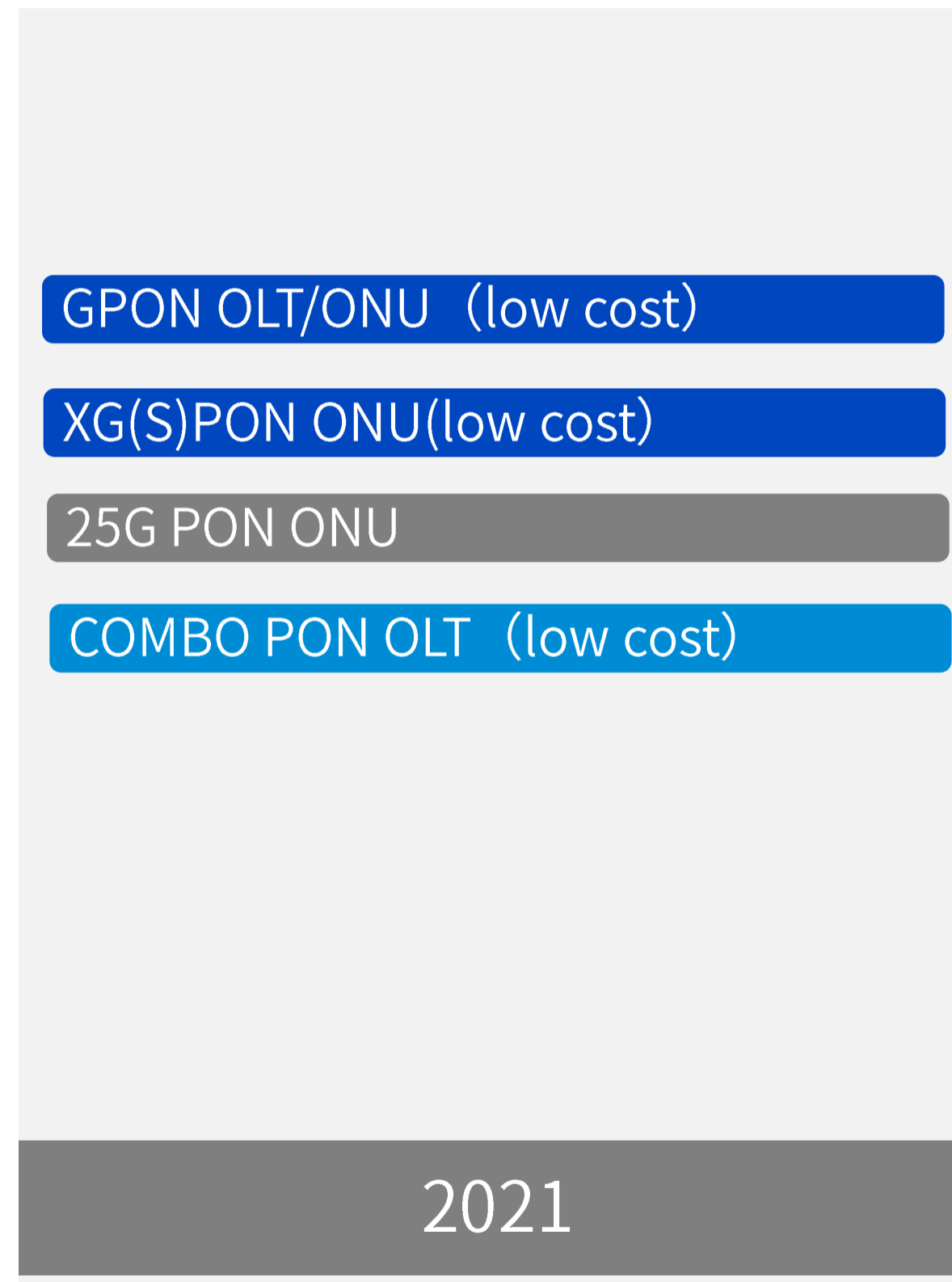
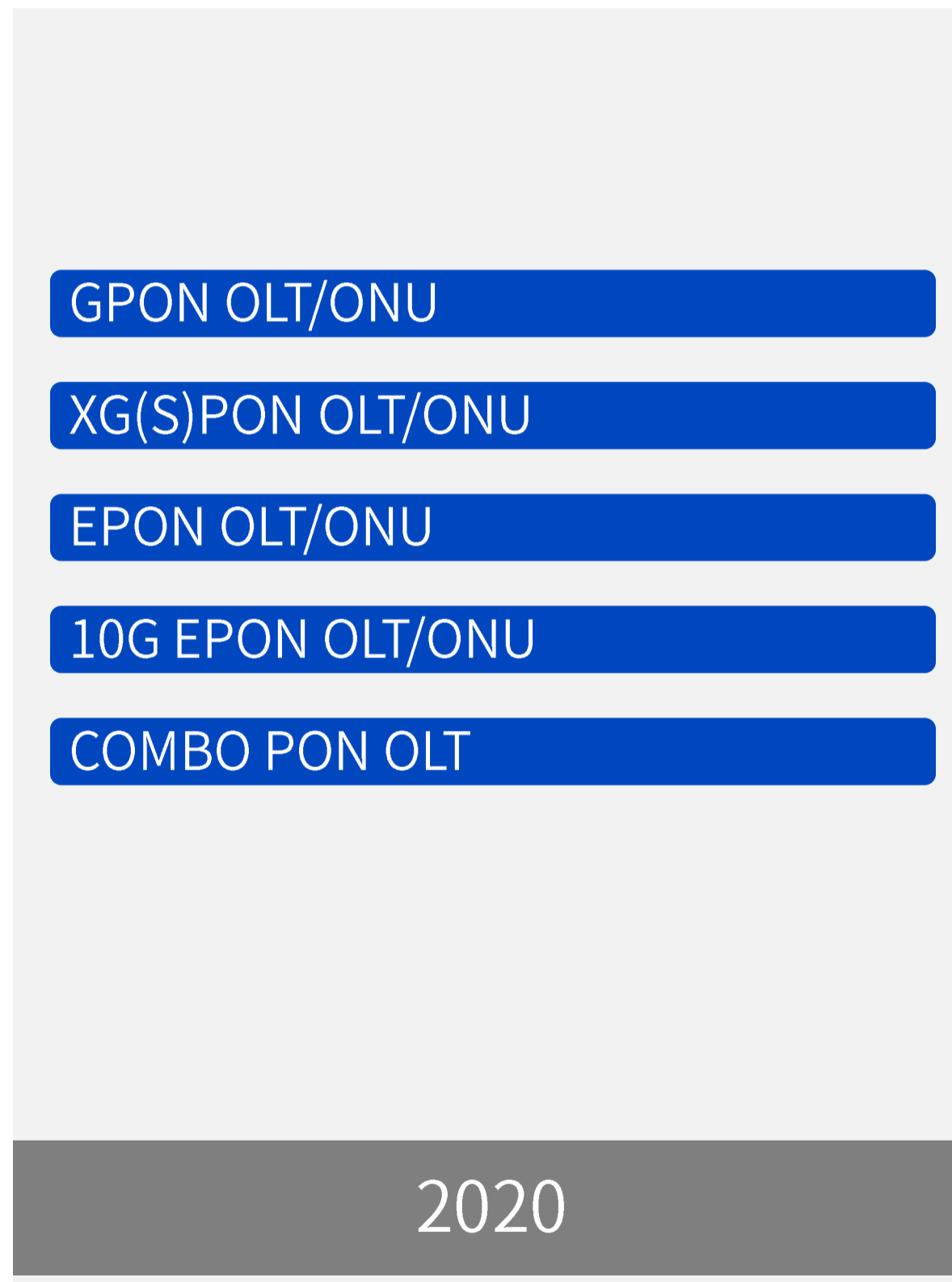
■ OSA

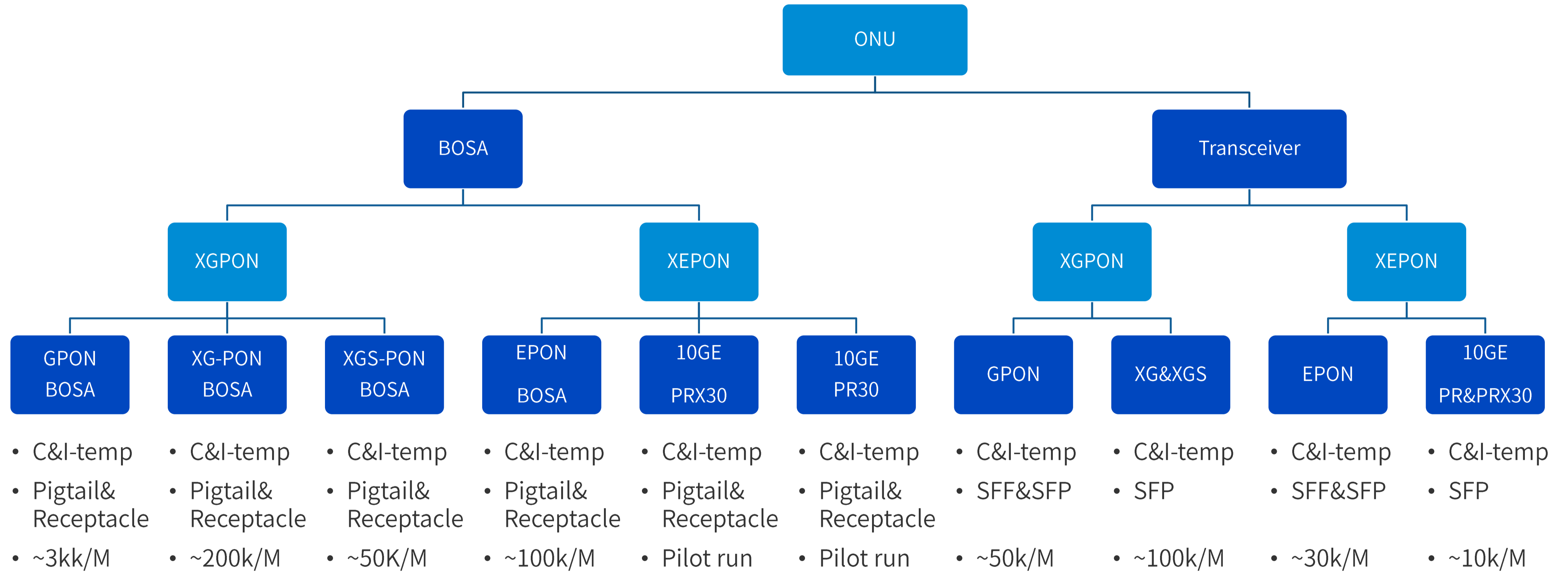
■ PON

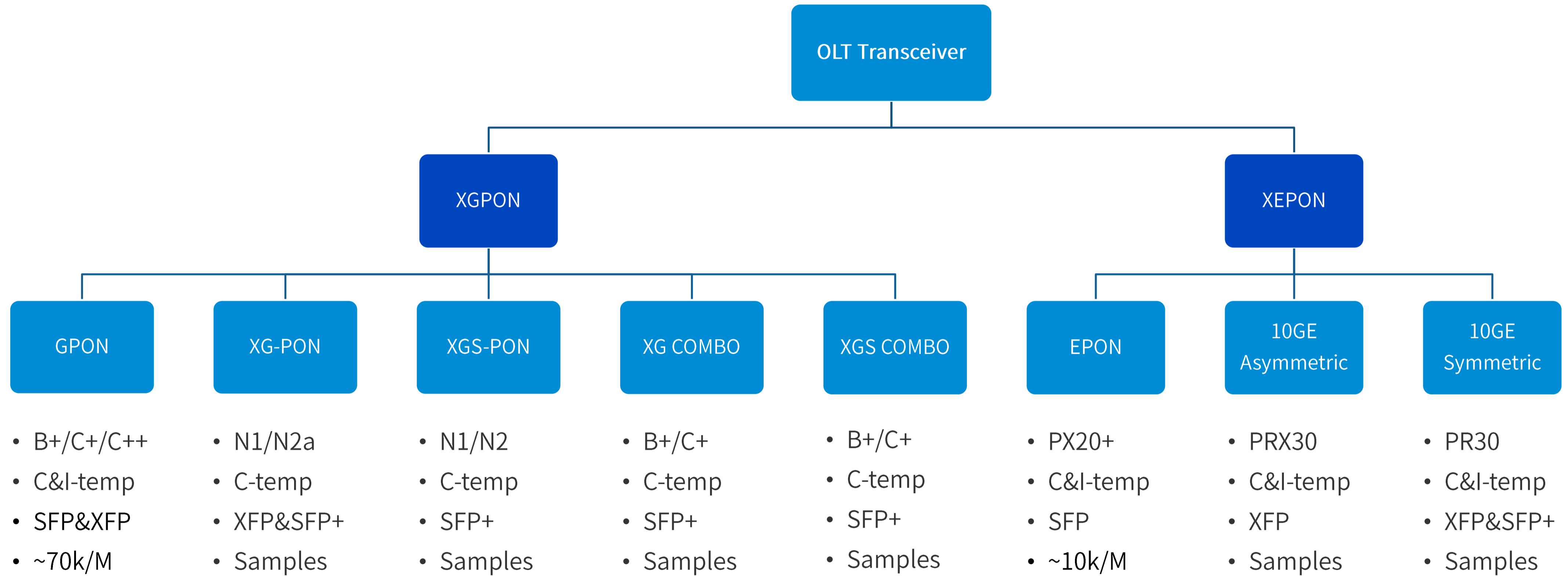


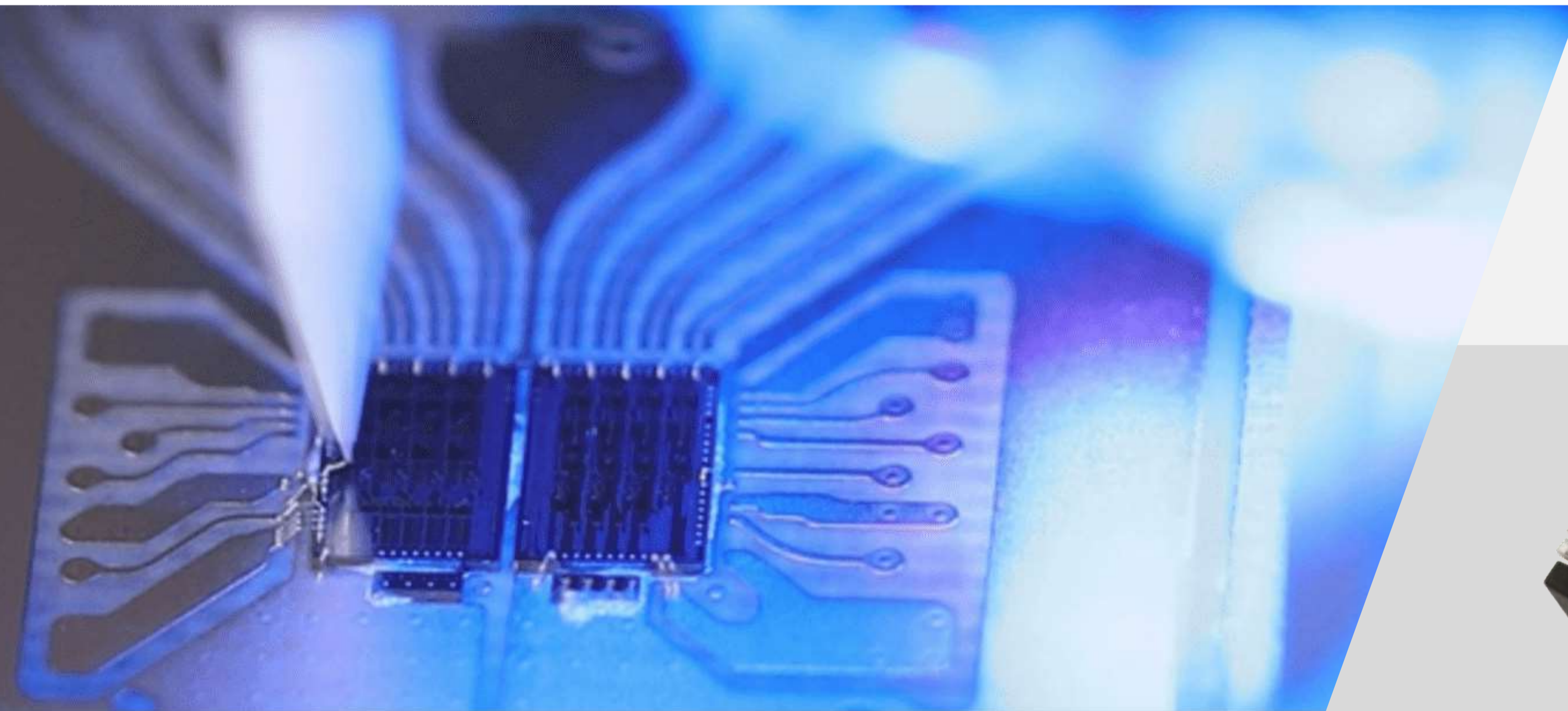
Access product development plan

MP/Try Run Feasibility study Plan

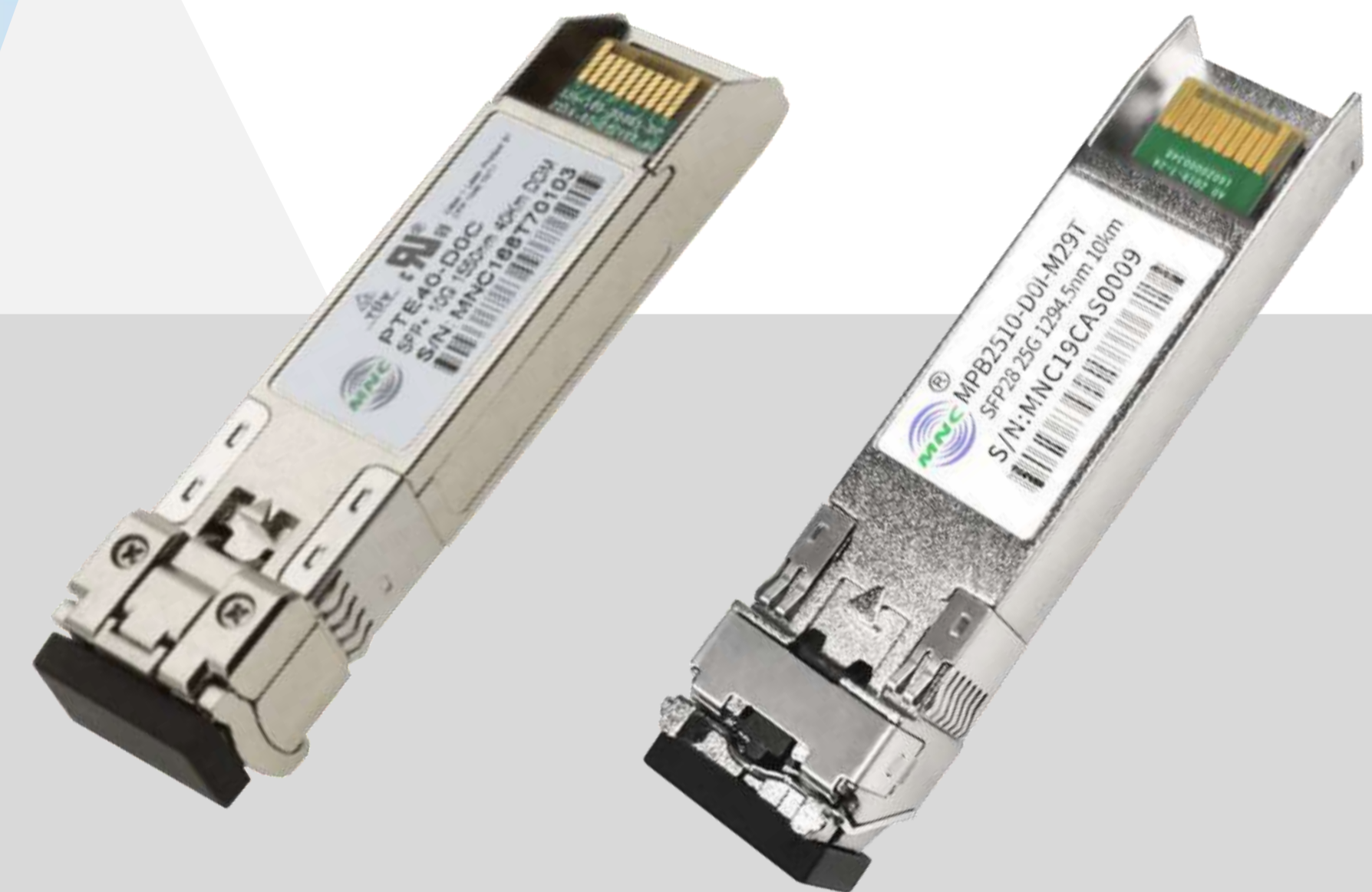




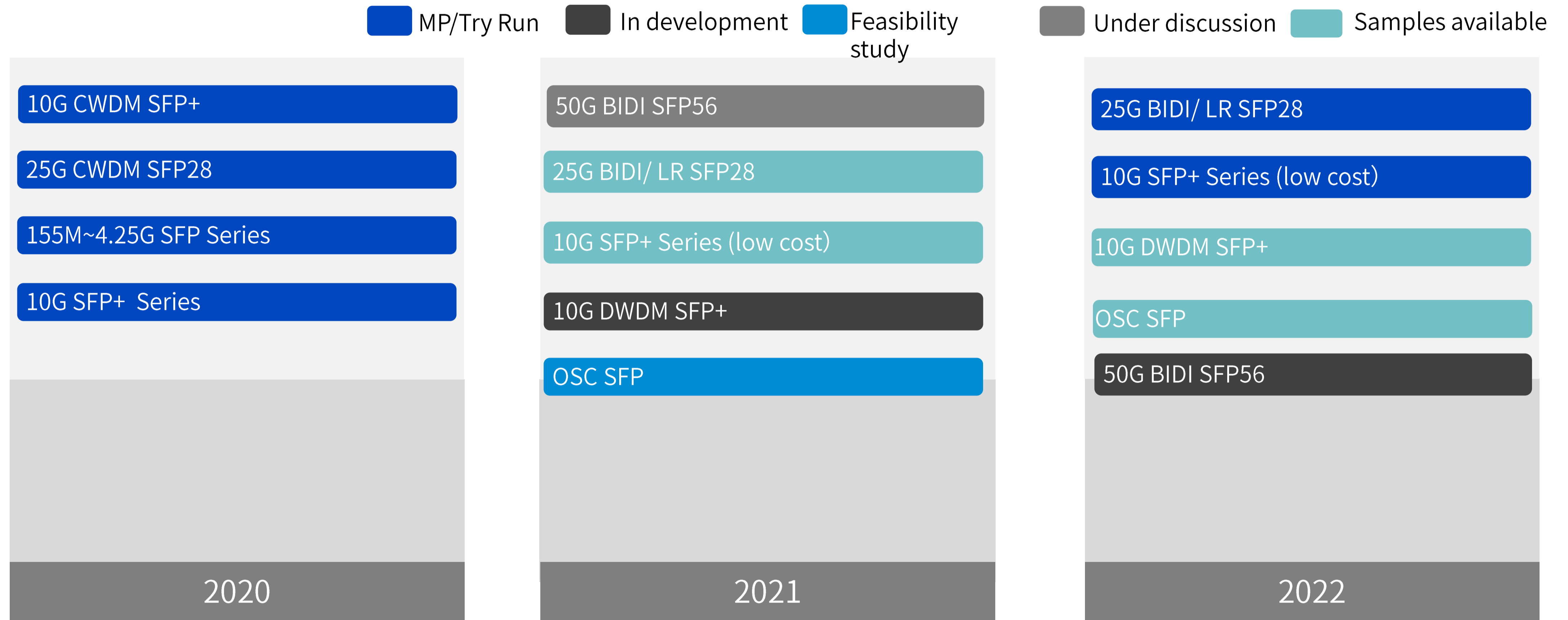




■ SFP/SFP+/XFP ■ 5G Frontend



5G product development plan



25G SFP28 Specification Table

Parameter	25G SFP28 LR	25G SFP28 BIDI	25G SFP28 CWDM	25G SFP28 LWDM	25G SFP28 MWDM	25G SFP28 DWDM
Distance	10km	10km	10km	10km	10km	10km
Wavelength	1310nm	1270/1330nm	CWDM	MWDM	LWDM	DWDM
Power dissipation	<1.5W	<1.5W	<1.5W	<2W	<2W	<2W
Transmitter	25G DML(DFB)	25G DML(DFB)	25G DML(DFB)	25G DML(DFB)	25G DML(DFB)	25G DML(DFB)
Receiver	25G PIN	25G PIN	25G PIN	25G PIN	25G PIN	25G PIN
Case Operating Temperature	-40°C to 85°C	-40°C to 85°C	-40°C to 85°C	-40°C to 85°C	-40°C to 85°C	-40°C to 85°C
Status	Mass production	Mass production	Mass production	Samples ready	Samples ready	Developing

- Up to 25.78 Gb/s rate
- Hot-pluggable SFP28 footprint
- 1310nm DFB laser transmitter
- Duplex LC connector
- RoHS2.0 compliant
- Up to 10 km on 9/125μm SMF
- Power consumption < 1.5W
- Single 3.3V power supply
- Industrial temperature range -40°C to +85°C

- Status: Mass production



- Up to 25.78 Gb/s rate
- Hot-pluggable SFP28 footprint
- 1270/1330nm DFB laser transmitter
- Single LC connector
- RoHS2.0 compliant
- Up to 10 km on 9/125 μ m SMF
- Power consumption < 1.5W
- Single 3.3V power supply
- Industrial temperature range -40°C to +85°C

- Status: Mass production



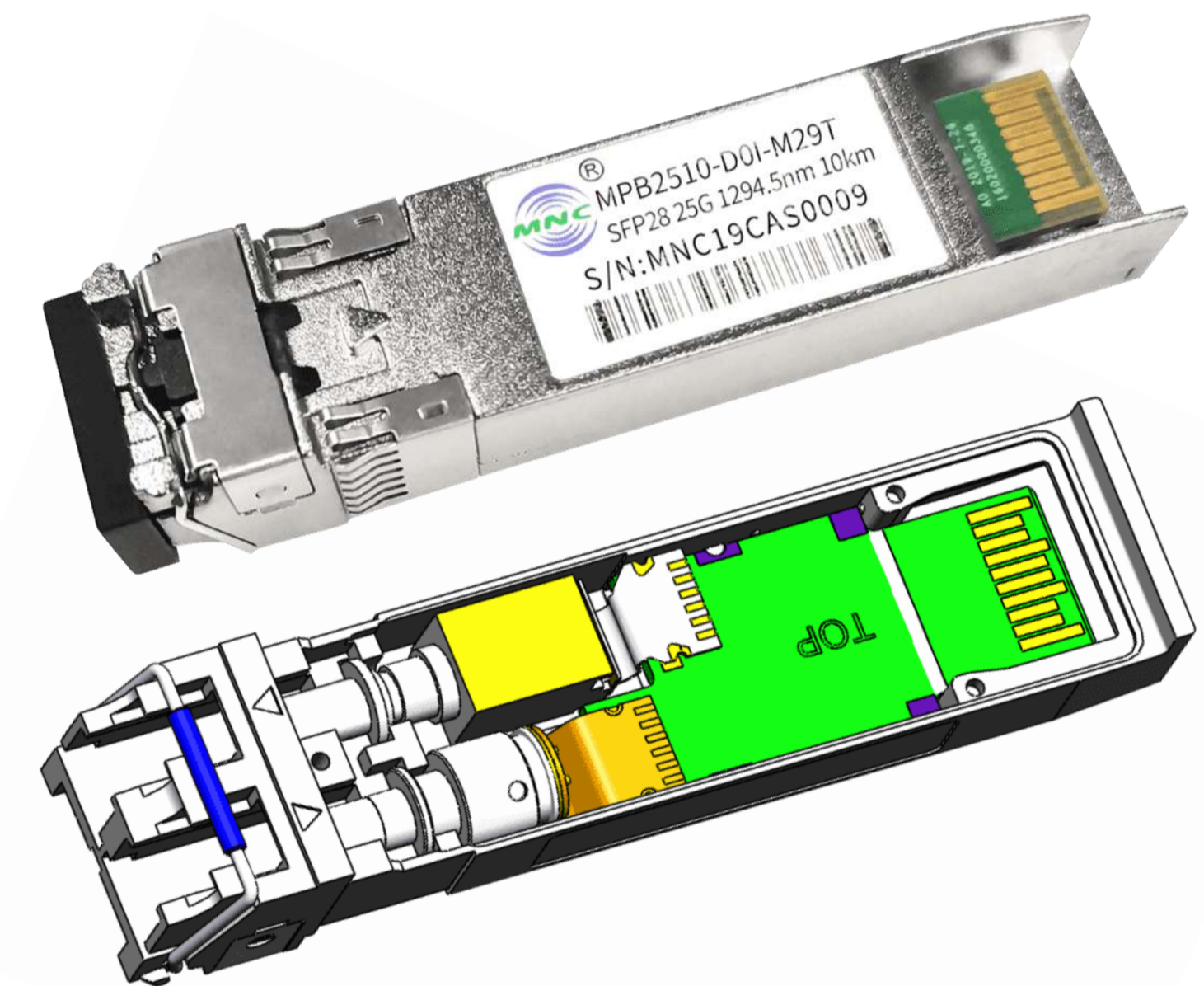
- Up to 25.78 Gb/s rate
- Hot-pluggable SFP28 footprint
- 1271/1291/1311/1331/1351/1371nm DFB laser transmitter
- Duplex LC connector
- RoHS2.0 compliant
- Up to 10 km on 9/125μm SMF
- Power consumption < 1.5W
- Single 3.3V power supply
- Industrial temperature range -40°C to +85°C

- Status: Mass production 300k/M



- Up to 25.78 Gb/s rate
- Hot-pluggable SFP28 footprint
- Cooled LWDM (1269.23~1318.35nm) DFB Laser and PIN photo detector
- Duplex LC connector
- RoHS2.0 compliant
- Up to 10 km on 9/125 μ m SMF
- Power consumption < 2W
- Single 3.3V power supply
- Industrial temperature range -40 $^{\circ}$ C to +85 $^{\circ}$ C

- Status: Samples ready



- Up to 25.78 Gb/s rate
- Hot-pluggable SFP28 footprint
- Cooled MWDM (1267.5~1374.5nm) DFB Laser and PIN photo detector
- Duplex LC connector
- RoHS2.0 compliant
- Up to 10 km on 9/125μm SMF
- Power consumption < 2W
- Single 3.3V power supply
- Industrial temperature range -40°C to +85°C

- Status: Samples ready



10G SFP+ Specification Table

Parameter	10G SFP+ LR	10G SFP+ BIDI	10G SFP+ CWDM
Distance	10km	10km	10km
Wavelength	1310nm	1270/1330nm	CWDM
Power dissipation	<1W	<1W	<1.5W
Transmitter	10G DML(DFB)	10G DML(DFB)	10G DML(DFB)
Receiver	10G PIN	10G PIN	10G PIN
Case Operating Temperature	-40°C to 85°C	-40°C to 85°C	-40°C to 85°C
Status	Volume shipping	Volume shipping	Volume shipping

- Hot-pluggable SFP+ footprint
- Up to 10km link length
- Supports 9.95 to 10.5 Gb/s bit rates
- Uncooled 1310nm DFB laser
- < 1W power dissipation
- Duplex LC connector
- RoHS2.0 compliant
- Single 3.3V power supply
- Industrial temperature range -40°C to 85°C

- Status: Mass production



- Hot-pluggable SFP+ footprint
- Up to 10km link length
- Supports 9.95 to 10.5 Gb/s bit rates
- Uncooled 1270/1330nm DFB laser
- < 1W power dissipation
- Single LC connector
- RoHS2.0 compliant
- Single 3.3V power supply
- Industrial temperature range -40°C to 85°C

- Status: Mass production



- Hot-pluggable SFP+ footprint
- Up to 10km link length
- Supports 9.95 to 10.5 Gb/s bit rates
- CWDM DFB Laser and PIN receiver
- < 1.5W power dissipation
- Duplex LC connector
- RoHS2.0 compliant
- Single 3.3V power supply
- Industrial temperature range -40°C to 85°C

- Status: Mass production



Data communication product line

■ High-speed optical module



■ AOC



Development plan

■ MP
 ■ Samples available Q3 MP
 ■ Made-to-order
 ■ 2022Y

	Single Channel	Two Channel	Four Channel	Eight Channel
100G base Single Lambda 100G PAM4 (50G Band rate)	100G DR 100G FR 100G LR		400G DR4 400G FR4	
50G base PAM4 (25G Band rate)	50G SR 50G DR 50G FR	100G SR2		400G SR8
25G base NRZ (25G Band rate)	25G LR 25G SR 25G AOC		100G CWDM4 100G LR4 100G SR4 100G AOC	200G SR8
10G base NRZ (10G Band rate)	10G LR 10G SR 10G AOC		40G LR4 40G SR4 40G AOC	

Transceiver - 10G&25G SR



Part. No	Specifications							
	Package	Connector	Rate (Gbps)	Laser (nm)	Fiber Type (nm)	Reach*1 (m)	Case Temp (°C)	DDM
MPTED3-D0C-8VT1	SFP+	LC	10.3125	850	MMF	300	0~70	Y
MPB25D1-D0C-8VT1	SFP28	LC	25.78125	850	MMF	100	0~70	Y

Note*1: 10G: OM2 fiber 100m, OM3 fiber 300m; 25G: Typical OM2 fiber 70m, OM3 fiber 100m

Transceiver - 40G&100G SR4



Part. No	Specifications							
	Package	Connector	Rate*1 (Gbps)	Laser (nm)	Fiber Type (nm)	Reach*2 (m)	Case Temp (°C)	DDM
MQA4ZD2-DMC-8VT1	QSFP+	MPO	10.3125	850	MMF	300	0~70	Y
MQBG1D1-DMC-8VT1	QSFP28	MPO	25.78125	850	MMF	100	0~70	Y

Note*1: For each channel

Note*2: 10G: OM2 fiber 100m, OM3 fiber 300m; 25G: Typical OM2 fiber 70m, OM3 fiber 100m



Part. No	Specifications							
	Package	Connector	Rate*1 (Gbps)	Laser*2 (nm)	Fiber Type (nm)	Reach (m)	Case Temp (°C)	DDM
MQBG102-D0C-T1	QSFP28	LC	25.78125	CWDM	SMF	2km	0~70	Y

Note*1: For each channel

Note*2: Typical wave length: 1271nm, 1291nm, 1311nm, 1331nm

Transceiver - 100G LR4 (COB&BOX)

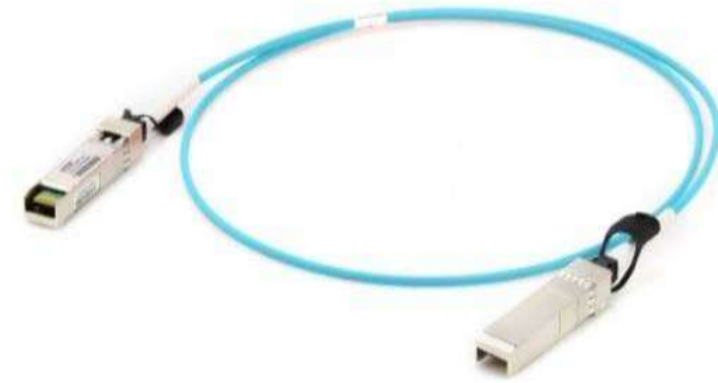


	Specifications							
	Package	Connector	Rate*1 (Gbps)	Laser*2 (nm)	Fiber Type (nm)	Reach (m)	Case Temp (°C)	DDM
MQBG110-D0C-T1	QSFP28	LC	25.78125	LWDM	SMF	10km	0~70	Y
MQBG110-D0I-T1	QSFP28	LC	25.78125	LWDM	SMF	10km	-40~85	Y

Note*1: For each channel

Note*2: Typical wave length: 1295.56nm, 1300.05nm, 1304.58nm, 1309.14nm

AOC - P2P AOC



Part. No*1	Specifications							
	Package	Connector	Rate (Gbps)	Laser (nm)	Fiber Type (nm)	Reach*2 (m)	Case Temp (°C)	DDM
MPTED3-DZC-XXXT	SFP+	-	10.3125	850	MMF	1-300	0~70	Y
MPB25D1-DZC-XXXT	SFP28	-	25.78125	850	MMF	1-100	0~70	Y
MQA4ZD2-DZC-XXXT	QSFP+	-	4x10.3125	850	MMF	1-300	0~70	Y
MQBG1D1-DZC-XXXT	QSFP28	-	4x25.78125	850	MMF	1-100	0~70	Y

Note*1: XXX means cable length(m)

Note*2: 10G: Typical OM2 cable<100m, OM3 cable<300m; 25G: Typical OM3 cable<70m, OM4 cable<100m

AOC - Breakout AOC



Part. No*1	Specifications							
	Package	Connector	Rate (Gbps)	Laser (nm)	Fiber Type (nm)	Reach*2 (m)	Case Temp (°C)	DDM
MQA4ZD1-DBC-XXXT	QSFP+ SFP+	-	4x10.3125	850	MMF	1-300	0~70	Y
MQBG1D1-DBC-XXXT	QSFP28 SFP28	-	4x25.78125	850	MMF	1-100	0~70	Y

Note*1: XXX means cable length(m)

Note*2: Typical OM2 cable<100m, OM3 cable<300m; 25G: Typical OM3 cable<70m, OM4 cable<100m

AOC - Breakout AOC(Pigtail)



Part. No*1	Specifications							
	Package	Connector	Rate (Gbps)	Laser (nm)	Fiber Type (nm)	Reach*2 (m)	Case Temp (°C)	DDM
MQA4ZD1-D0C-XXXT	QSFP+	LC	4x10.3125	850	MMF	1-300	0~70	Y
MQBG1D1-D0C-XXXT	QSFP28	LC	4x25.78125	850	MMF	1-100	0~70	Y

Note*1: XXX means cable length(m)

Note*2: 10G: Typical OM3 cable<300m; 25G: Typical OM3 cable<70m, OM4 cable<100m

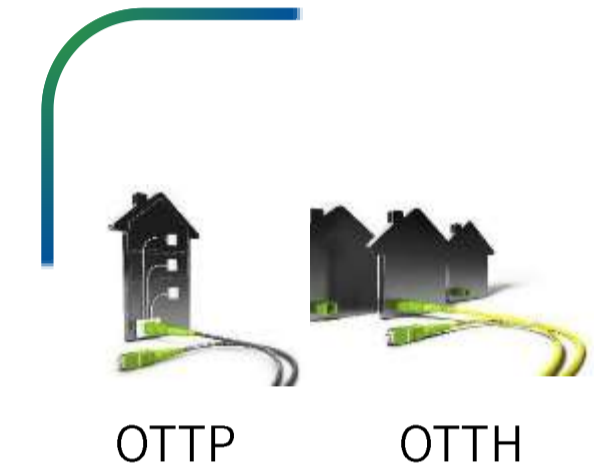
Key Products – Product Applications



Switch



OTN/SPN



Optical Access



ONU



4G/5G



Data Center

mentech

Optical BU – Partners

In no particular order

ZTE中兴

FiberHome

ZOWEE

BROADCOM®

SK telecom

中国移动
China Mobile

RAISECOM

TP-LINK®

NOKIA

NEC

中国电信
CHINA TELECOM

中怡数宽

TwoWin

COMMSCOPE®

SERCOM

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mentech